

HSF Property:ROHS

ACER  
BAP41/BAP51/BAP52/BXP41/SJM52  
UMA+Discrete(SW Gfx)  
MAIN BOARD

2009.06.30

Tuesday, June 30, 2009		A02
DATE	CHANGE NO.	REV

<http://www.vinafix.vn>

	EE	DATE	POWER	DATE	INVENTEC			
DRAWER					BAP41/BAP51 (Montevina SFF)			
DESIGN								
CHECK								
RESPONSIBLE								
SIZE:					I VER:			
FILE NAME: XXXXXXXXXXX-XX								
P/N	XXXXXXXXXXXX				SIZE	CODE	DOC NUMBER	REV
					C	A02	D-CS-1310A2282001-ALG	A02
					SHEET	1	of	48

# 1. Schematic Page Description :

## Montevina Schematic Ver : A02

1. Title

2. Schematic Page DESCR

3. Block Diagram

4. Annotations

5. Schematic Modify

6. Timing Diagram

7. Power Block Diagram

8. Adaptor in/Charge

9. 5VLA/5VA/3VA

10. 3VS/5VS/1.5V (DDR3)

11. 1.05VS/1.5S/1.8V/1.5VA

12. Power Latch/1.5VS/SCREW HOLE

13. CPU Core Power

14. GPU Core Power

15. Penryn Processor(1/2)

16. Penryn Processor(2/2)

17. CPU Thermal

18. Cantiga Host(1/6)

19. Cantiga DMI/Graph(2/6)

20. Cantiga DDRIII(3/6)

21. Cantiga Power(4/6)

22. Cantiga Power(5/6)

23. Cantiga Ground(6/6)
24. Clock Generator

25. DDR3 SDRAM SO-DIMM0

26. DDR3 SDRAM SO-DIMM1

27. ICH9M CPU/SATA(1/4)

28. ICH9M PCI/PCIE/DMI/USB(2/4)

29. ICH9M GPIO(3/4)

30. ICH9M Power/GND(4/4)

31. LCD/CRT

32. KBC ITE8502E-L

33. IO CN

34. IO CN

35. IO CN

36. Audio Codec

37. EASY PORT CN/ LEVEL SHIFTER

38. M92-S2(1/5)

39. M92-S2(2/5)

40. M92-S2(3/5)

41. M92-S2(4/5)

42. M92-S2(5/5)

43. DDR3 VRAM

44. HyBrid Switch

45. dGPU Power

46. dGPU Power

47. dGPU Power

48. HDD Board

49. TPM Board

# Vinafix 3 Blo



# 4. Net name Description :

## Voltage Rails

DCIN	Primary DC system power supply
+5VLA	5.0V always on power rail by LATCH or ACIN
+5VA	5.0V always on power rail by ECPWON
+3VA	3.3V always on power rail by ECPWON
+5VS	5.0V switched power rail by SLP_S3#_3R
+3VS	3.3V switched power rail by SLP_S3#_3R
+1.8VS	1.8V switched power rail by SLP_S3#_3R
-----	
VCC_CORE	Core Voltage for CPU
+1.05VS	1.05V power rail for AGTL+ termination/Core for GMCH by SLP_S3#_3R
+1.25VS	1.25V switched power rail by SLP_S3#_3R
+1.5VS	1.5V power rail for CPU PLL/DMI;PCIE;DDRIII DLLs for GMCH/Core;PCIE for ICH9m by SLP_S3#_3R
-----	
+1.5V	1.5V power rail for DDRII by SLP_S5#_3R
0.75VDDT_DDRIII	0.75V DDRII Termination Voltage by SLP_S3#_3R

## Part Naming Conventions

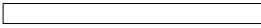



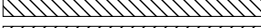



C	=	Capacitor
CN	=	Connector
D	=	Diode
F	=	Fuse
L	=	Inductor
Q	=	Transistor
R	=	Resistor
RP	=	Resistor Pack
U	=	Arbitrary Logic Device
Y	=	Crystal and Osc

## Net Name Suffix

#	=	Active Low signal
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# 5. Board Stack up Description

## PCB Layers

Layer 1		Component Side, Microstrip signal Layer
Layer 2		Ground Plane
Layer 3		Stripline Layer
Layer 4		Power Plane
Layer 5		Stripline Layer
Layer 6		Stripline Layer
Layer 7		Ground Plane
Layer 8		Solder Side, Microstrip signal Layer

	Differential Impedance for Microstrip	Differential Impedance for Stripline
Host Clock	95 ohm +/- 20%	95 ohm +/- 20%
PCI-E Clock	95 ohm +/- 20%	95 ohm +/- 20%
DDR3 CLK	75 ohm +/- 20%	75 ohm +/- 20%
DDR3 Strobe	90 ohm +/- 20%	90 ohm +/- 20%
DMI Bus	95 ohm +/- 20%	95 ohm +/- 20%
PCIE Bus	95 ohm +/- 20%	95 ohm +/- 20%
SDVO	95 ohm +/- 20%	95 ohm +/- 20%
SATA	95 ohm +/- 20%	95 ohm +/- 20%
USB	90 ohm +/- 20%	90 ohm +/- 20%
LVDS	95 ohm +/- 20%	95 ohm +/- 20%
Lan	95 ohm +/- 20%	95 ohm +/- 20%

Power Rail	Destination	Voltage	S0 Current
VCC_CORE	Penryn SFF HFM: LFM:	1.3319V-1.4375V-1.4591V 0.9221V-0.9625V-0.9739V	18A
1.05VS	Penryn SFF : AGTL+ termination Cantiga GS: Core Cantiga GS: PCIE Cantiga GS:Core+IMEL+HSIO Cantiga GS:VCC_GMCH Cantiga GS:VCCA_SM_CK and NCTF Cantiga GS:VCC_DMI Cantiga GS:VCCA_SM Cantiga GS:VTT ICH9M:VCC1_05 ICH9M:DMI ICH9M:CPU_IO	1V-1.05V-1.10V 0.997V-1.05V-1.102V 0.9975V-1.05V-1.1025V 0.9975V-1.05V-1.1025V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V	4.5A 8.7A 1.78A 2.898A 10.154A 37.95mA 456mA 747.5mA 852mA 1.634A 48mA 2mA
1.5VS	Penryn SFF PLL Cantiga GS: QDAC Cantiga GS: LVDS Cantiga GS: TVDAC Cantiga GS: Various PLLS analog supply Cantiga GS: VCC_SM_CK Cantiga GS: VCC_SM ICH9M:PCIE_ICH ICH9M:SATA_ICH ICH9M:VCC_GLAN Mini Card: Express Card:	1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.71V-1.8V-1.89V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V	130mA 0.5mA 60.31mA 35mA 485mA 149.5mA 3.1625A 646mA 1.342A 80mA 650mA
1.5V	Cantiga GS: DDRIII System Memory	1.425V-1.5V-1.575V	3.1A(800M) 4.1A(1067M)
0.75VDDT_DDRIII	DDRIII:DDRIII Terminator:	0.7125V-0.75V-0.7875V	1.0A
3VS	Cantiga GS: HV CMOS Cantiga GS: VCCS_TV DAC ICH9M:VCC3_3 ICH9M:VCCGLAN3_3 Thermal Sensor: Mini Card: UMTS Express Card: CLK Generator: ICS9LPRS365BKLFT Mini Card: WirelessLan Bluetooth: Super I/O: IT8305E Azalia Codec: ALC262 Azalia MDC:	3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	105.3mA 78mA 308mA 1mA 5mA 1.3A 500mA
1.8VS	DVI	3.0V-3.3V-3.6V	120mA
3VA	ICH9M: RTC ICH9M:VCCSUS3_3 ICH9M:VCCCL3_3 ICH9M:VCCLAN3_3 LCD: Lan:AR8131 Azalia MDC: Flash ROM: BIOS	2V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	6uA 212mA 73mA 78mA 2A 1A
5VS	Cardreader: RTS5159 Azalia Codec: ALC269 HDD: SATA ODD: SATA Audio AMP: G1432 Inverter: WebCam	3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V	Max: 1.5A ; R/W: 460mA ; STDBY: 70mA Max: 1.5A ; R/W: 900mA ; STDBY: 45mA
5VA	USB: x 2 ports USB	5VA 5VA	1A 2A 1.5A
5VLA	Control Power		
3VLA	EC: ITE8512E	3.0V-3.3V-3.6V	300mA

<http://www.vinafix.vn>

INVENTEC

BAP41/BAP51 (Montevina SFF)

ANNOTATIONS

SIZE CODE DOC NUMBER REV  
Custom A02 D-CS-1310A2282001-ALG A02

CHANGE by Shun-Chin Chang DATE Monday, June 28, 2009

## 6. Schema

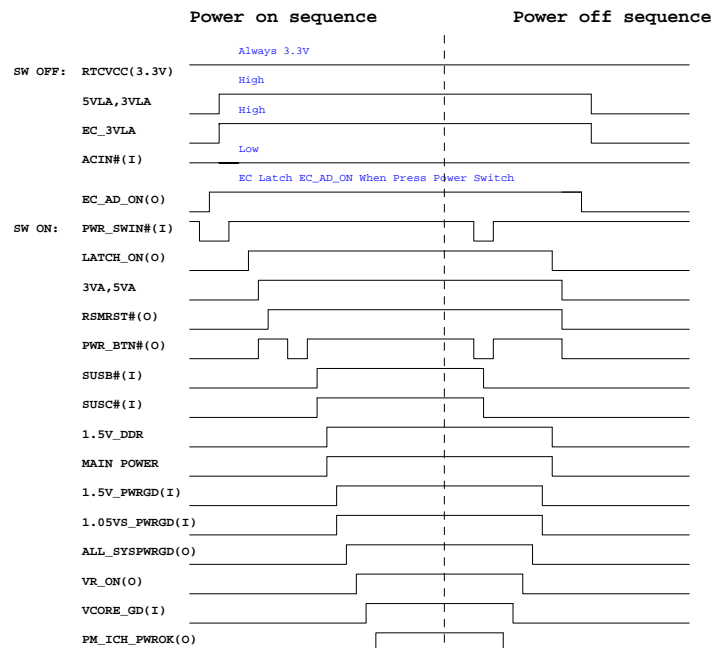
**<http://www.vinafix.vn>**

<b>INVENTEC</b>			
TITLE <b>BAP41/BAP51 (Montevina SFF)</b>			
Schematic Modify			
SIZE Custom	CODE A02	DOC NUMBER D-CS-1310A229201-ALG	REV A02
SHEET		5	of 49

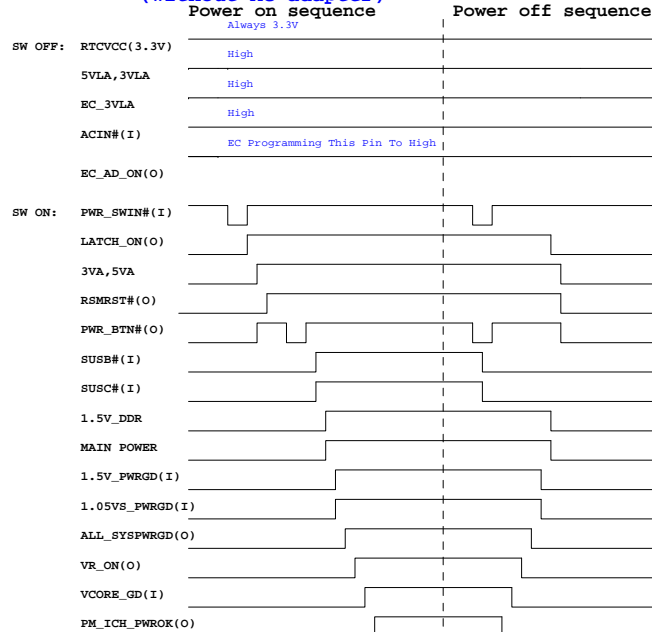
# SYSTEM POWER ON/OFF SEQUENCE

Drawing : Wendy, Huang

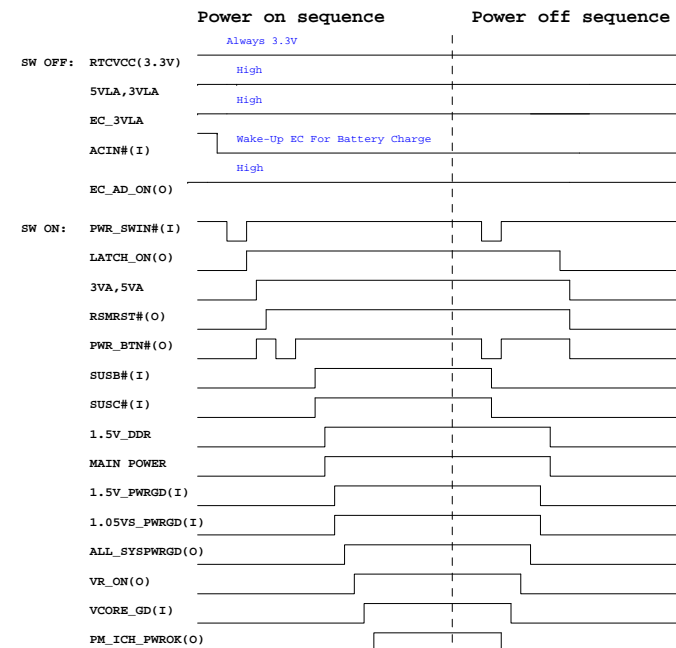
## Power on/off sequence AC insert (without Battery Pack)



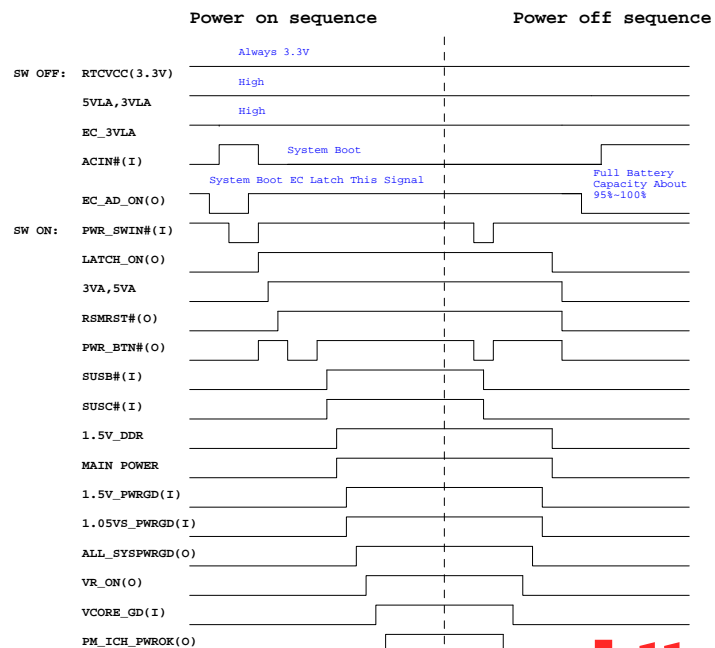
## Power on/off sequence Battery insert (without AC adapter)



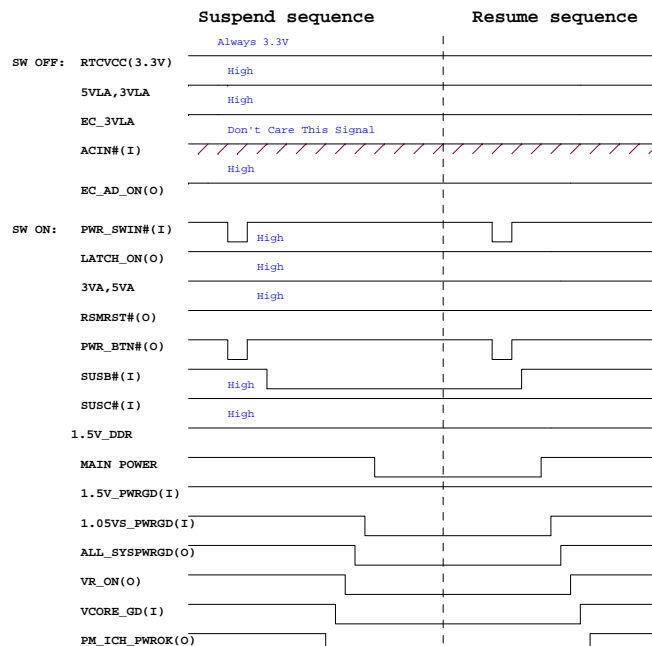
## Power on/off sequence AC insert(with charge over 95%)



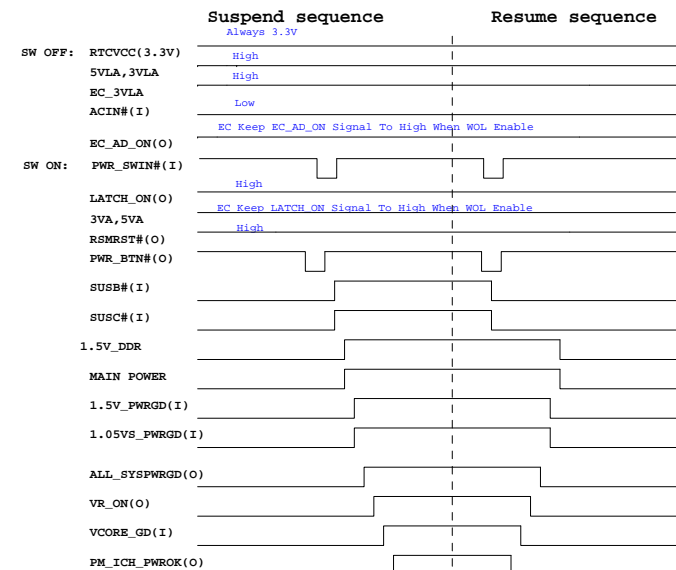
## Power on/off sequence AC insert(without charge over 95%)



## Suspend And Resume Sequence (S3)



## Power on/off sequence after windows shutdown (WOL enable)



<http://www.vinafix.vn>

INVENTEC

FILE  
BAP41/BAP51 (Montevina SFF)  
Title Diagram

SIZE CODE  
Custom A02

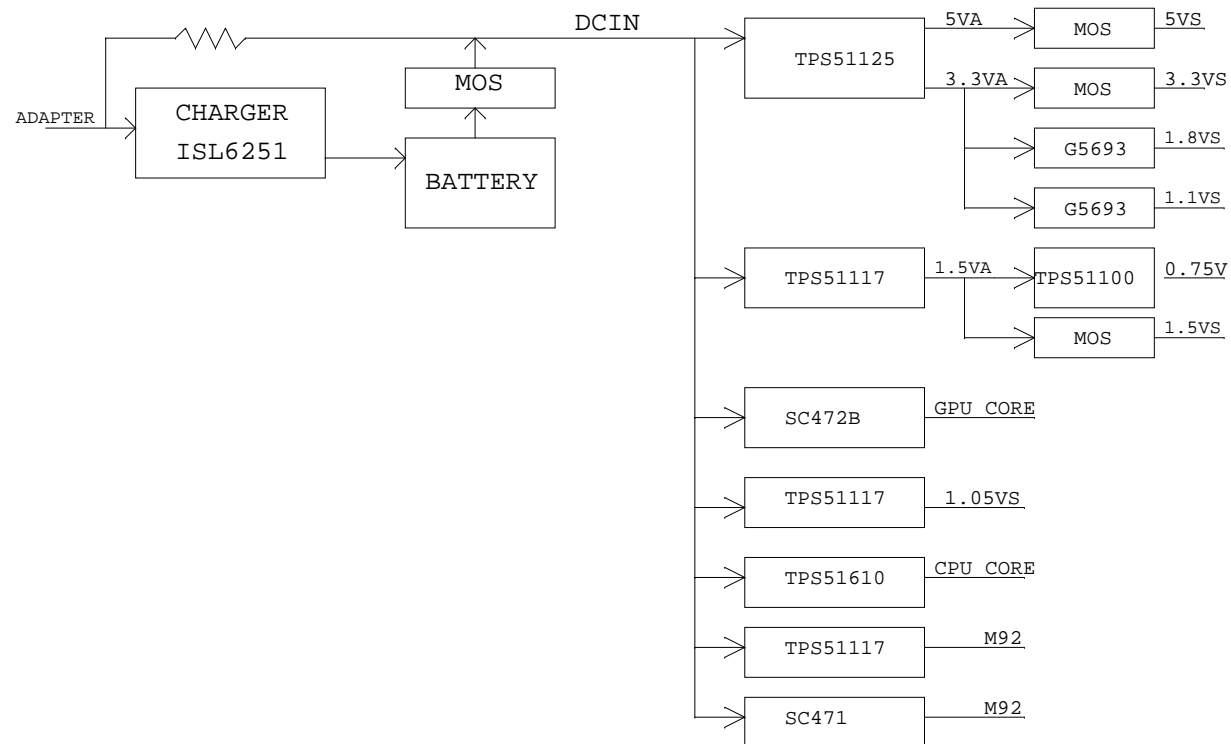
DOS NUMBER  
D-CS-1310A2292001-ALG

REV  
A02

CHANGE by Shun-Chin Chan DATE Monday, June 29, 2009

SHEET 6 of 49

# Power Block Diagram :

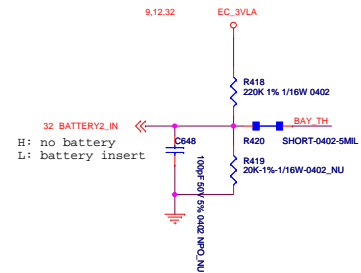
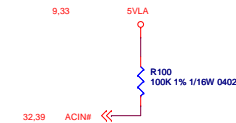
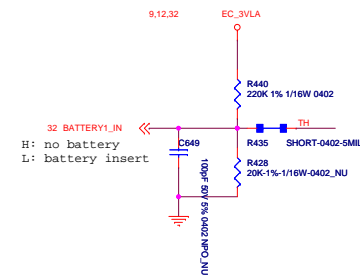
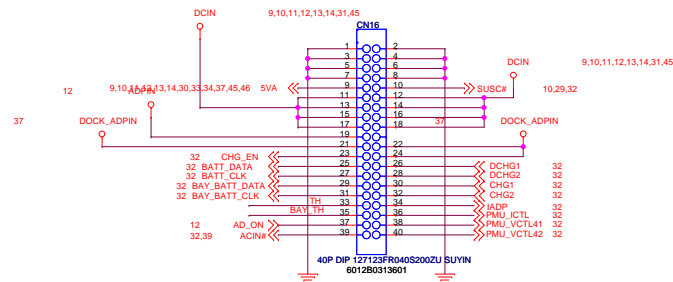


<http://www.vinafix.vn>

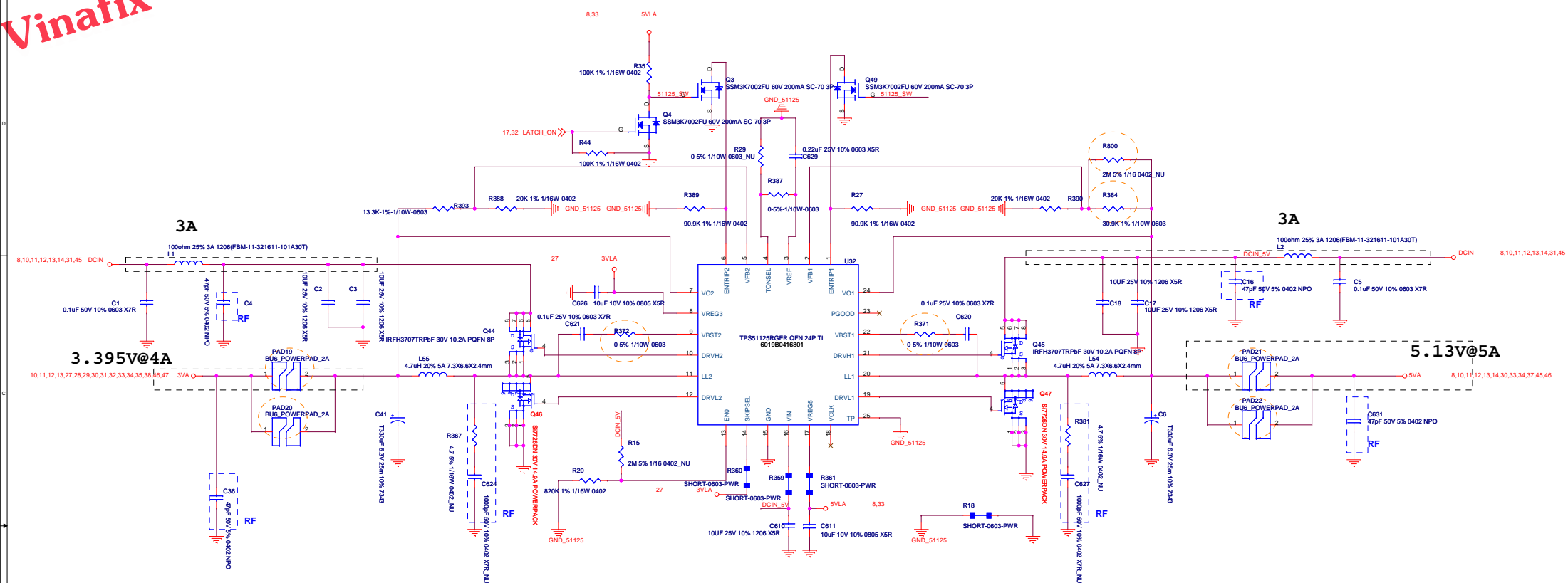
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TITLE: BAP41/BAP51 (Montevina SFF)			
Power Block Diagram			
SIZE	CODE	DOC NUMBER	REV
C	A02	D-CS-1310A2282001-ALG	A02
SHEET 1 of 48			

CHANGE by Shun-Chin Chang DATE Monday, June 28, 2009

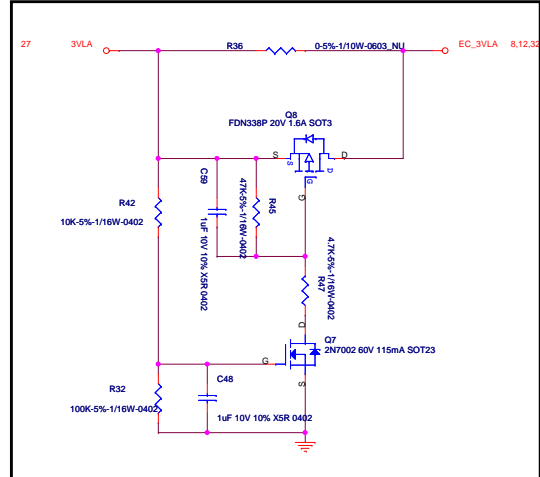
## Charger CN TO USIM/B



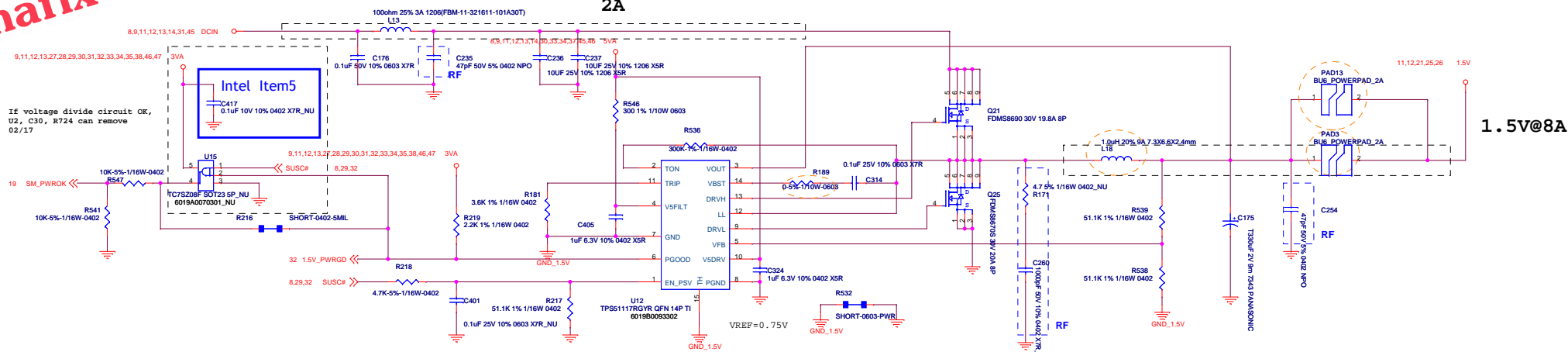




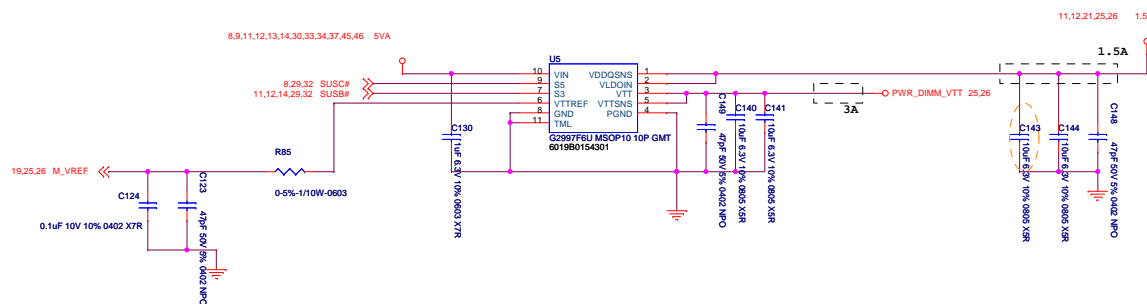
For Green PC



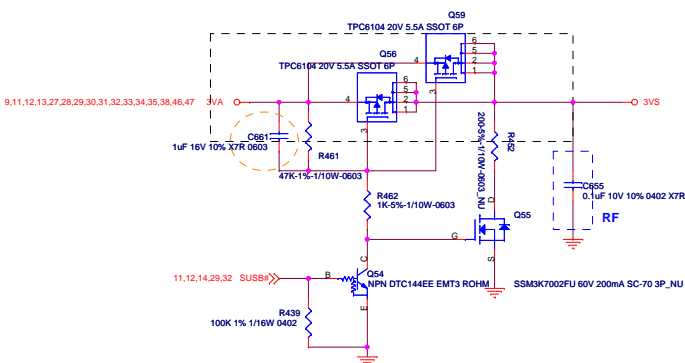
## 2A



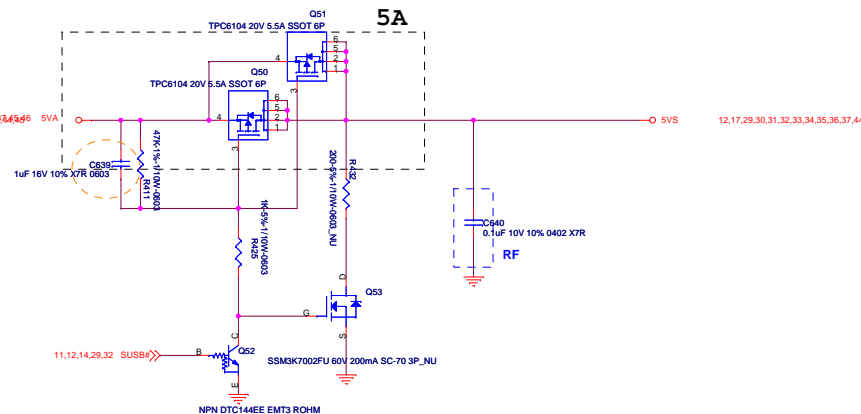
8,9,11,12,13,14,30,33,34,37,45,46 5VA

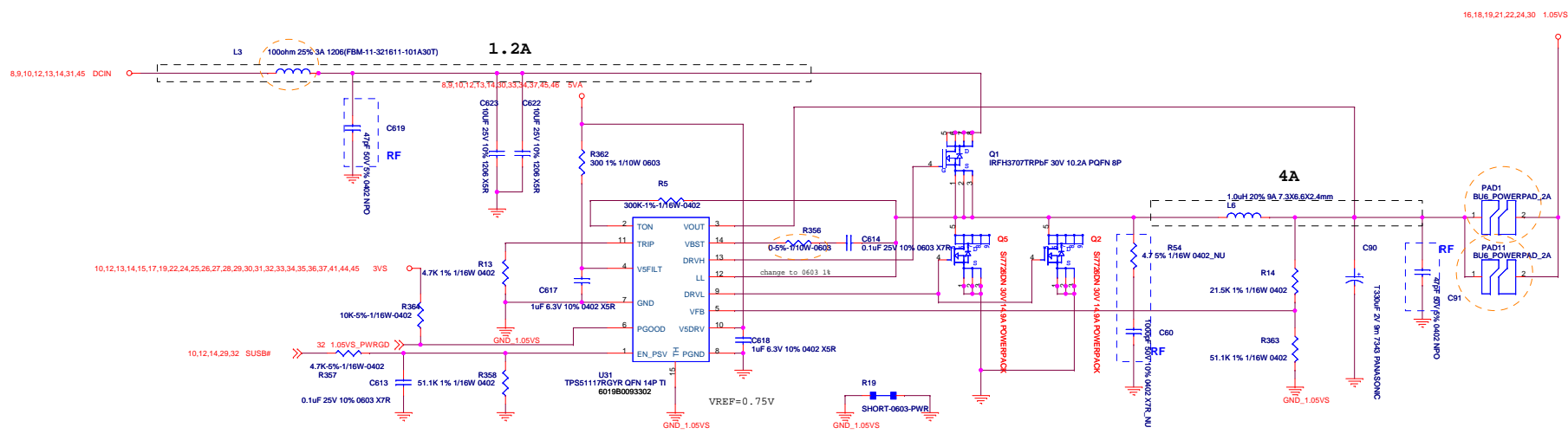
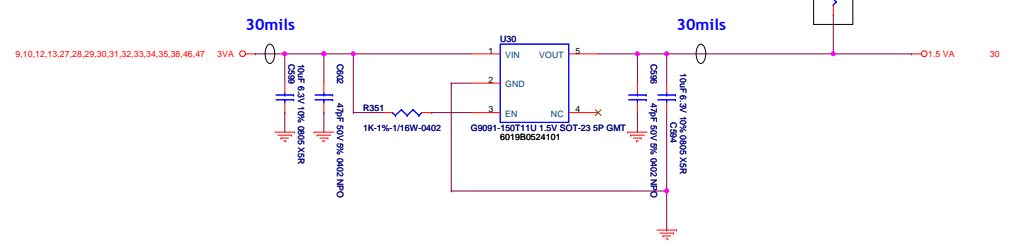
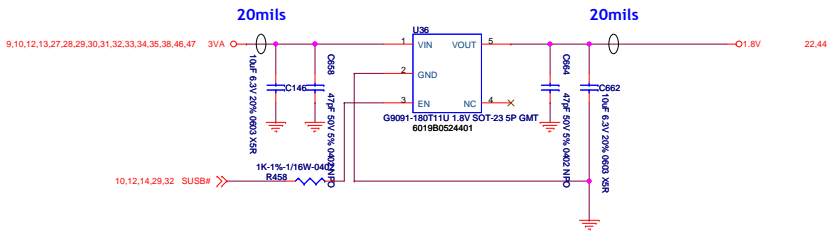


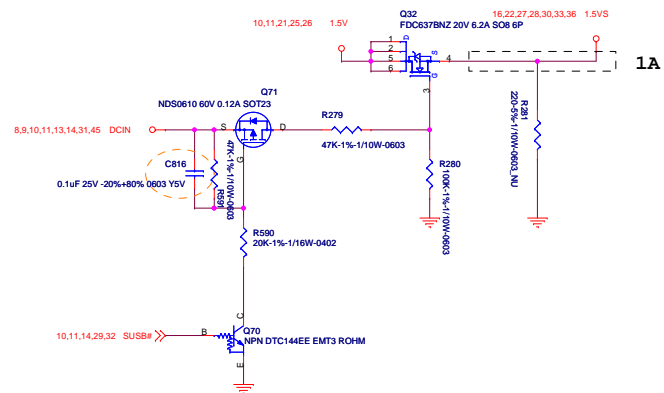
## 5A



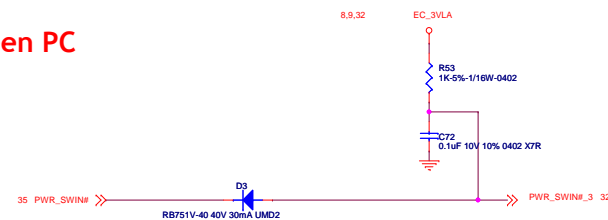
## 5A



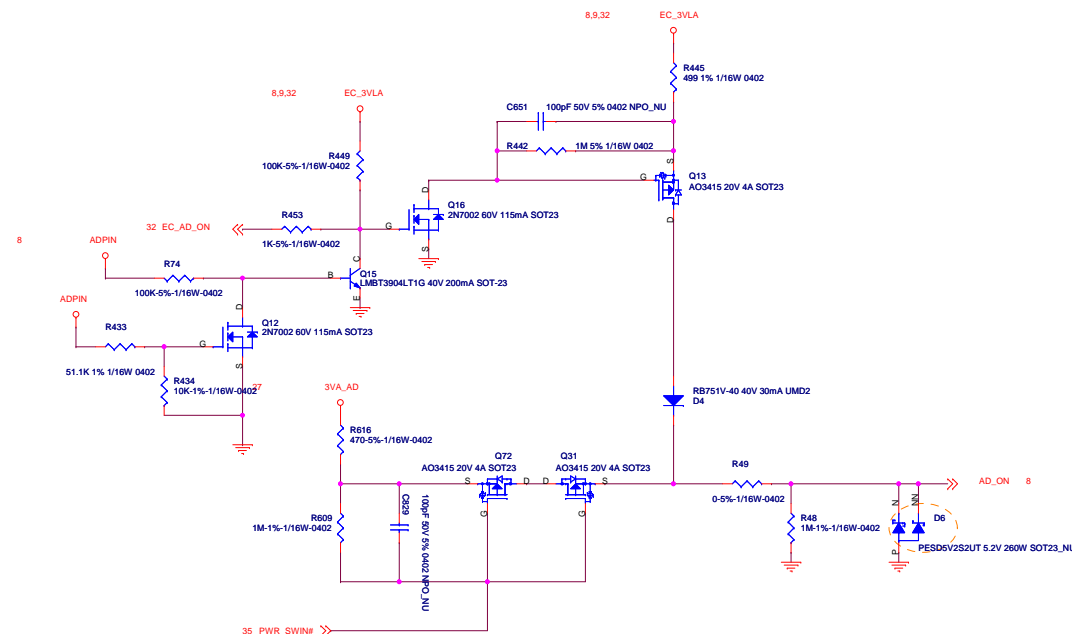




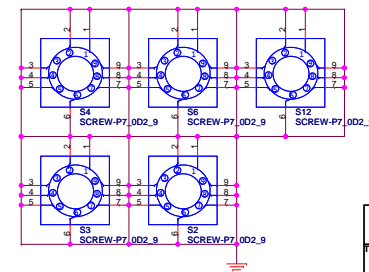
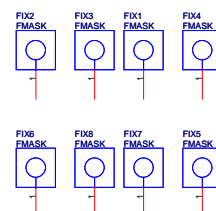
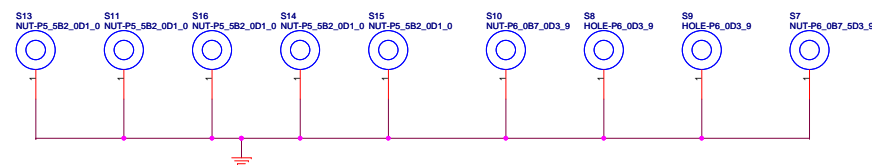
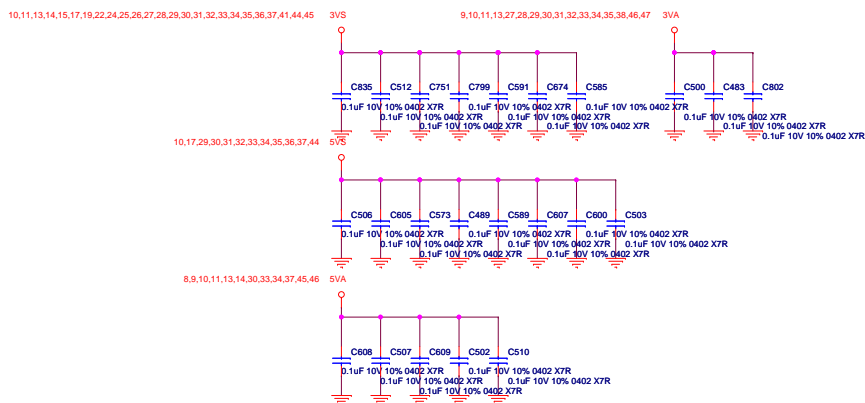
For Green PC



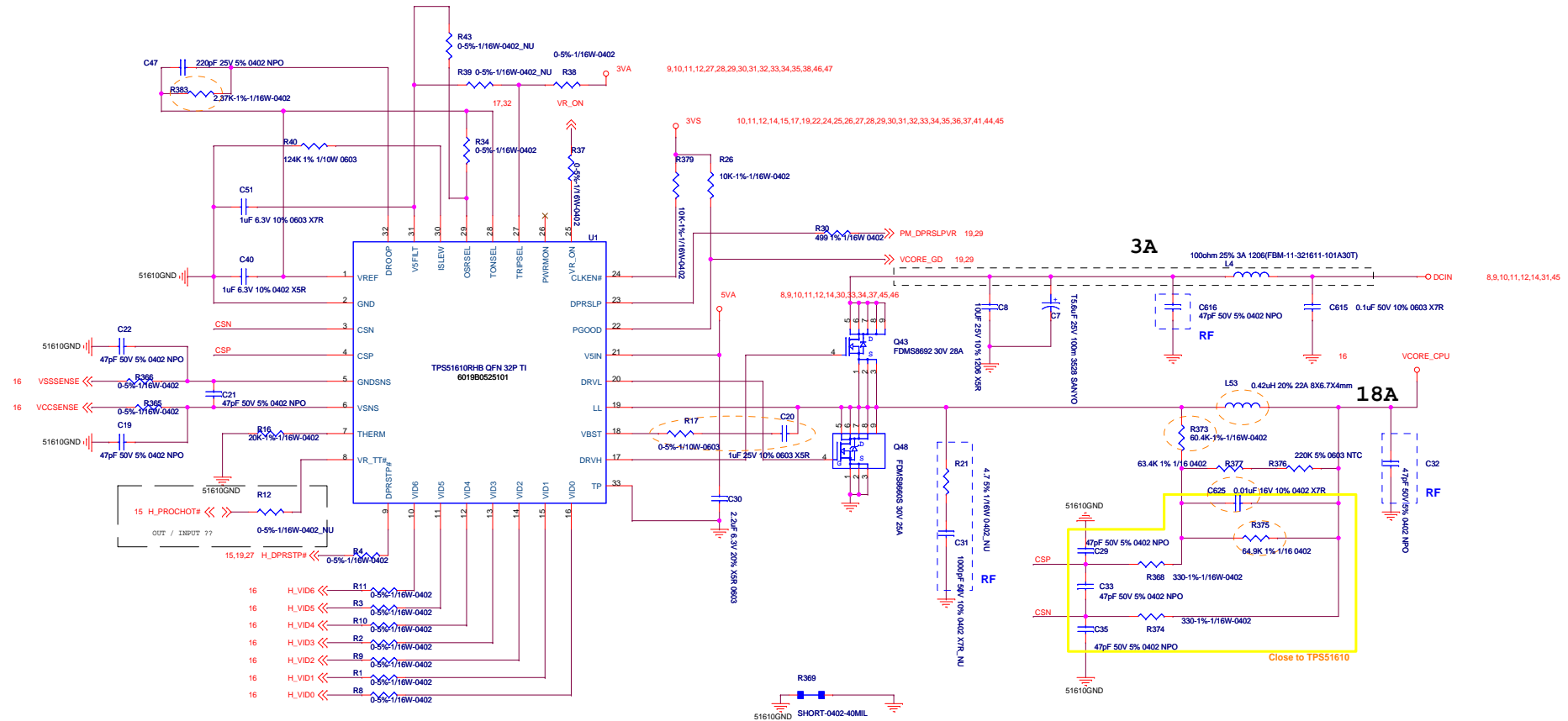
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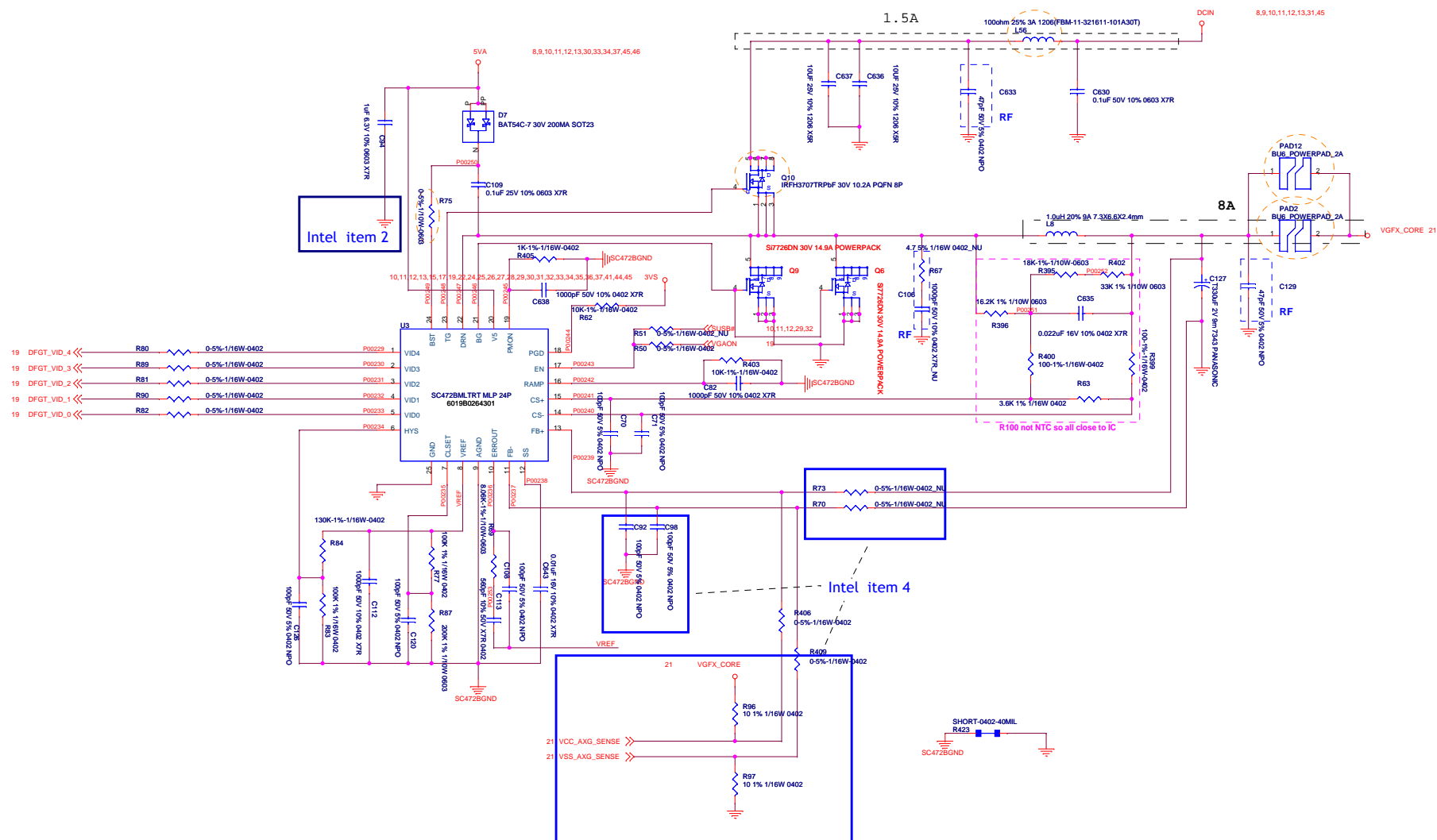


EMI Cap

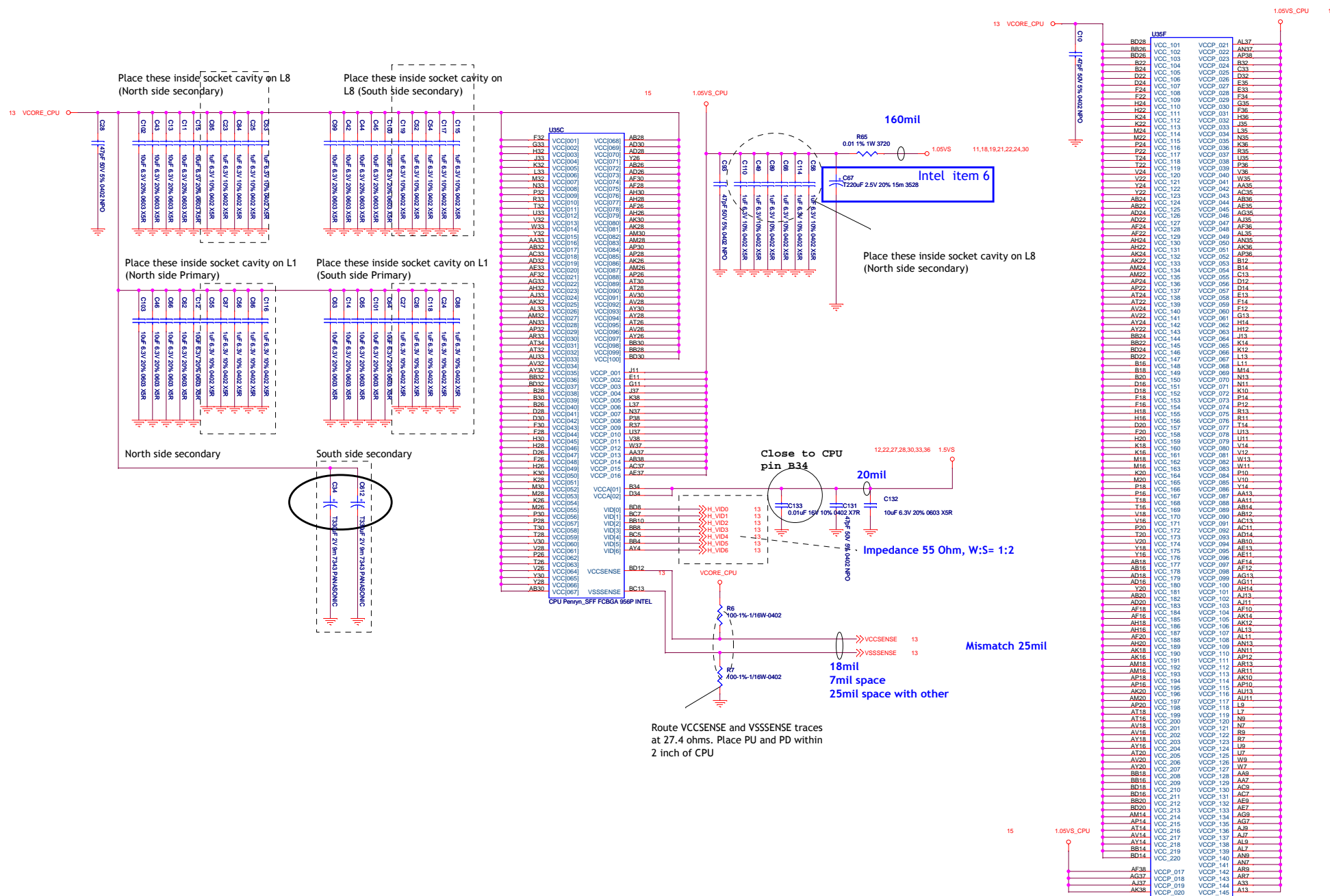


<b>INVENTEC</b>				
TITLE <b>BAP41/BAP51 (Montevina SFF)</b>				
<b>Power on latch</b>				
SIZE	CODE	DOC NUMBER	REV	
Custom	A02	D-CS-1310A2292001-ALG	A02	
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CPU Penryn\_SFF FCBGA 956P INTE  
6025B0091302

**INVENTEC**

**TITLE** BAP41/BAP51 (Montevina SF

**Penryn Processor(2/2)**

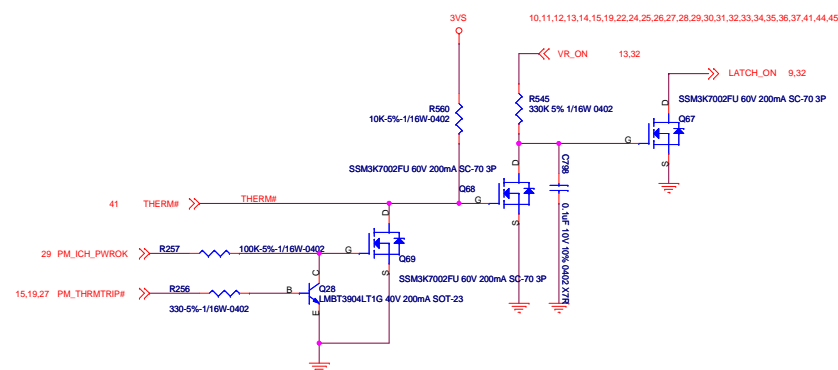
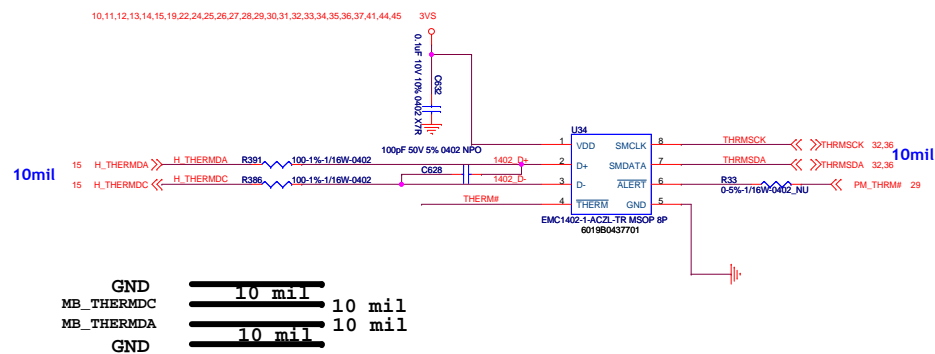
SIZE	CODE	DOC NUMBER
Custom	A02	D-CS-1310A2292001-ALG

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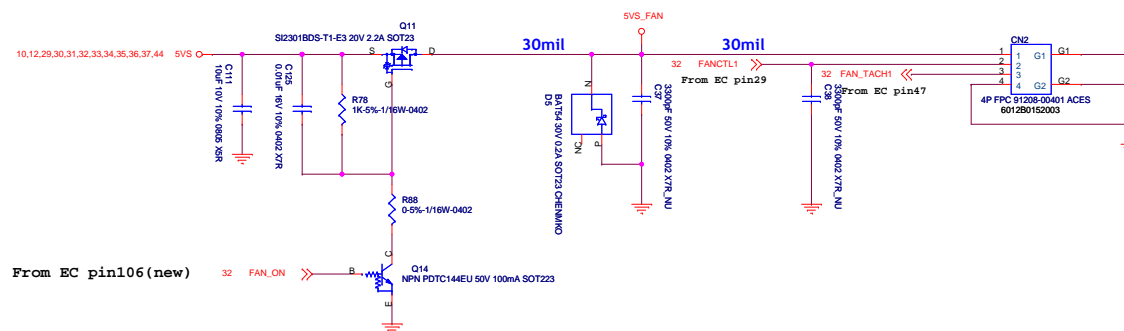
CHANGE by	Shun-Chin Chang	DATE	Thursday, July 02, 2009
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## THERMAL SENSOR

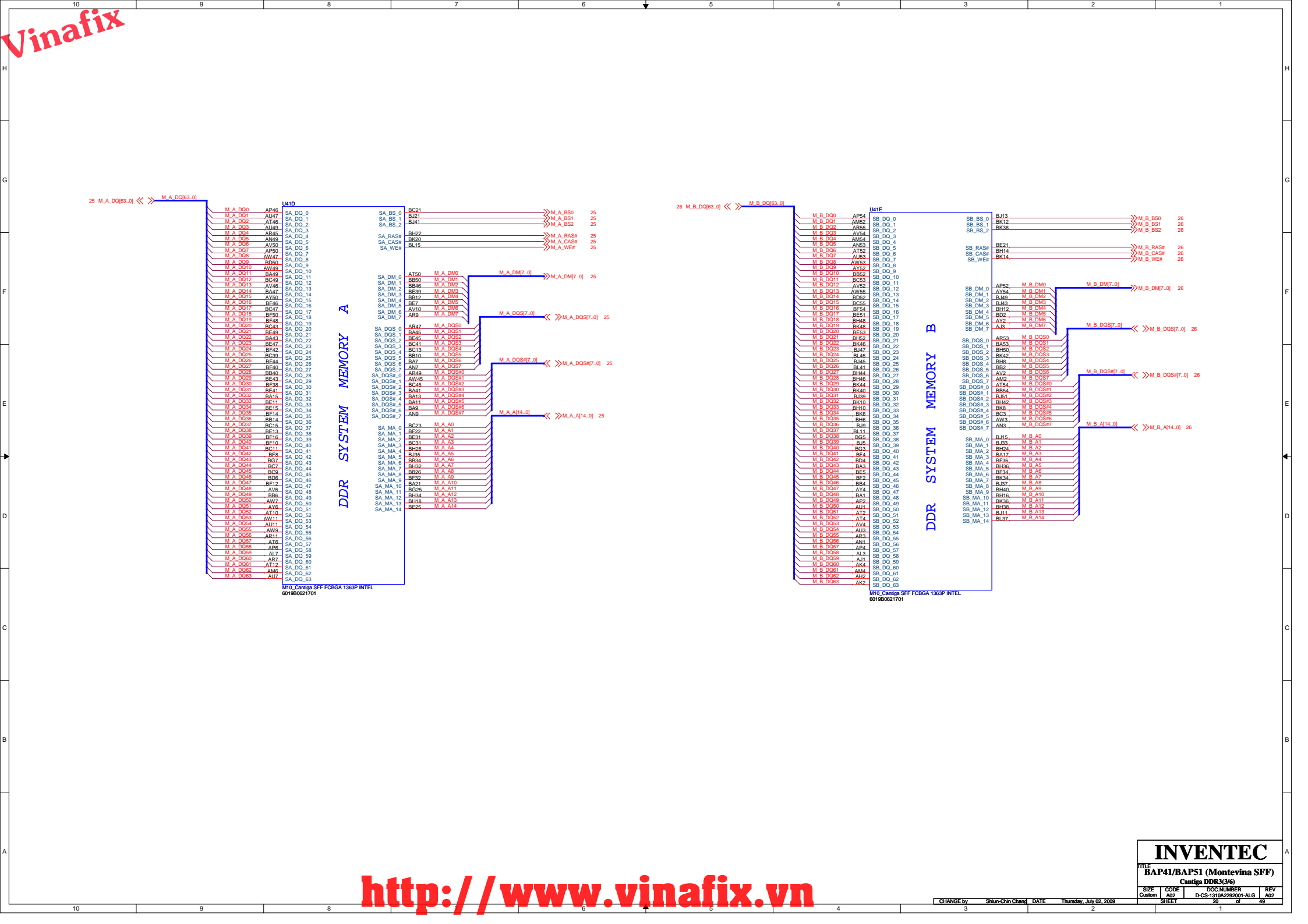


## Fan control







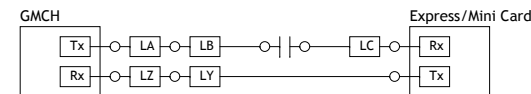
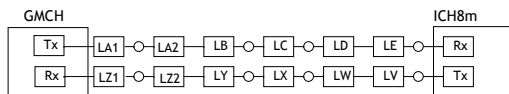








## PCIE Routing Guideline

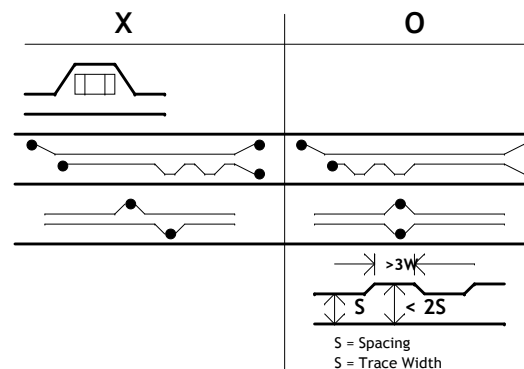
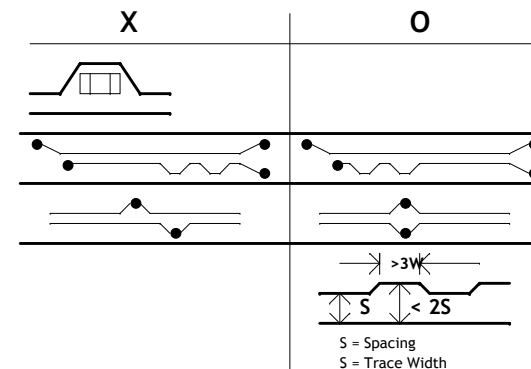


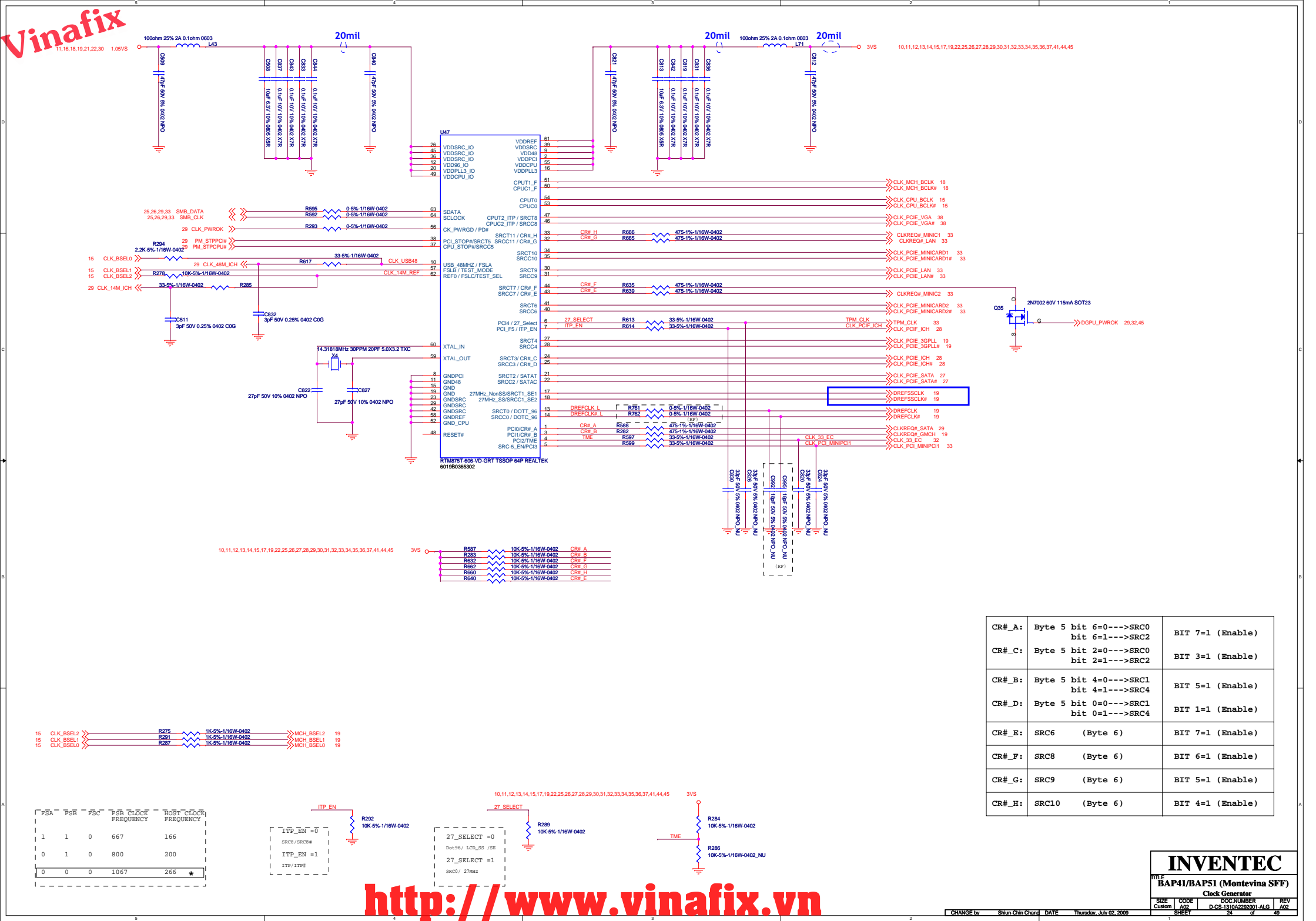
Breakout/in LA/LZ	Main Route LB/LV		Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip

Breakout/in LA/LZ	Main Route LB/LC/LY	Main Route LD/LW	Breakout/in LE/LV
Stripline	Microstrip	Same Routing layer as LE/LV	Microstrip

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	
Nominal Differential Trace Space	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 20 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Spits/Voids	No routing over plane splits No routing over voids	
Trace Length-LA (ICH7m Breakout)	Max = 400 mils	
Trace Length-LB (ICH7m Breakout to AC ap)	Max = 10750 mils	
Trace Length-LC (AC cap to PCIe CN)	Max = 10750 mils	
Trace Length-L1 (LA+LB+LC)	Max = 12000 mils	
Trace Length-LY (PCIe CN to ICH7m Breakout)	Max = 11950 mils	
Trace Length-LZ (ICH7m Breakout)	Max = 400 mils	
Trace Length-L2 (LY+LZ)	Max = 12000 mils	

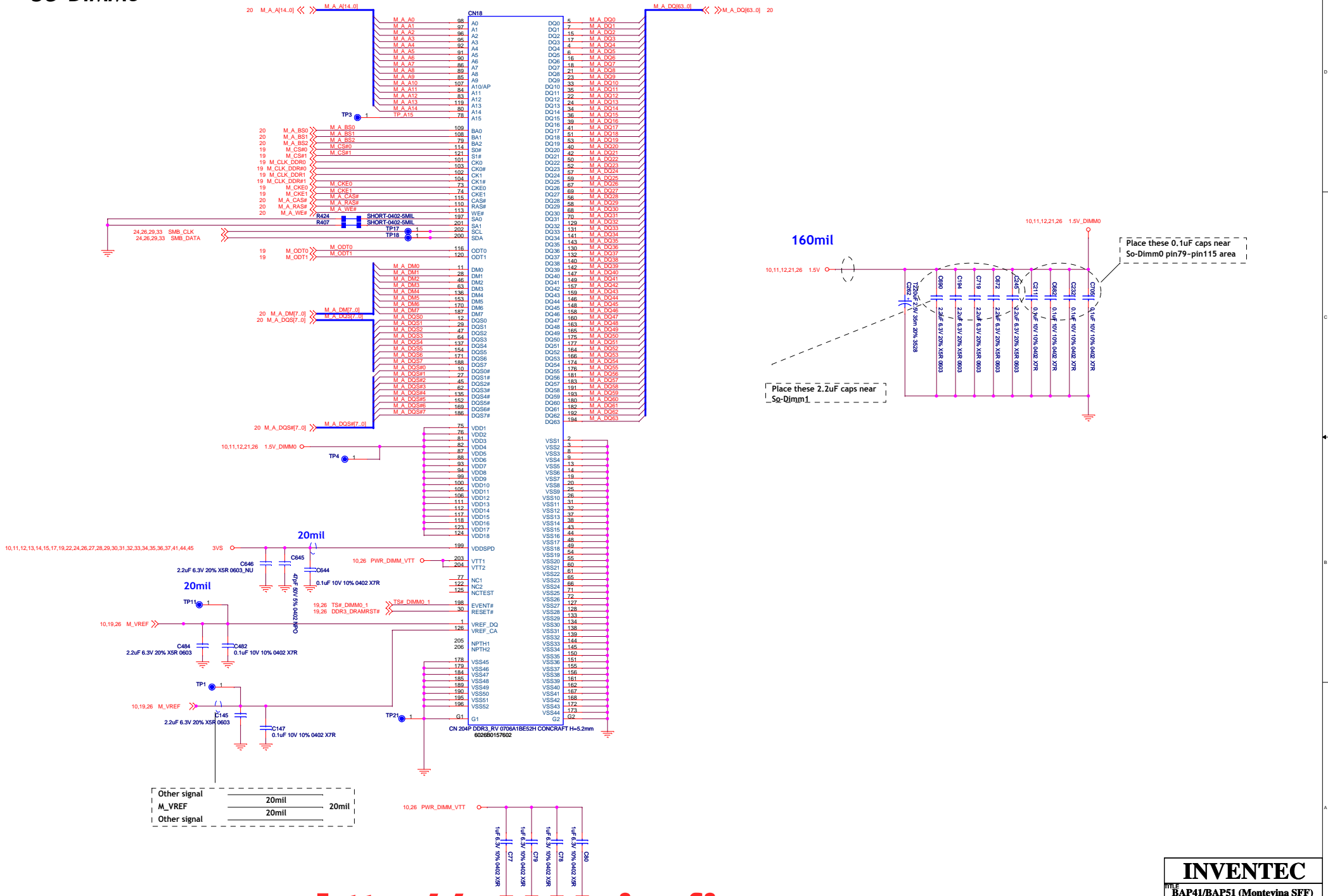
\*\*\* Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils



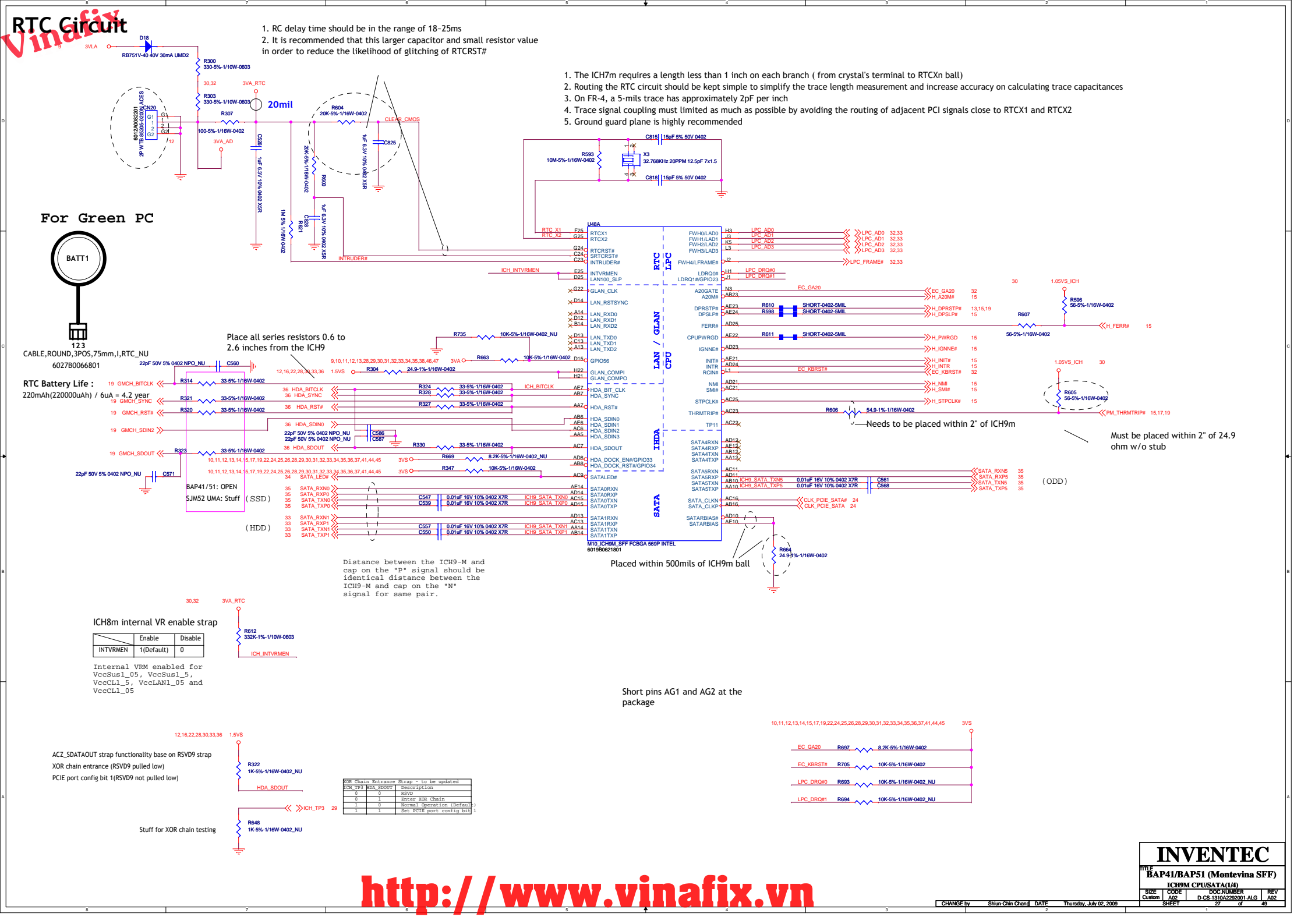


CR#_A:	Byte 5 bit 6=0--->SRC0 bit 6=1---->SRC2	BIT 7=1 (Enable)
CR#_C:	Byte 5 bit 2=0--->SRC0 bit 2=1---->SRC2	BIT 3=1 (Enable)
CR#_B:	Byte 5 bit 4=0--->SRC1 bit 4=1---->SRC4	BIT 5=1 (Enable)
CR#_D:	Byte 5 bit 0=0--->SRC1 bit 0=1---->SRC4	BIT 1=1 (Enable)
CR#_E:	SRC6 (Byte 6)	BIT 7=1 (Enable)
CR#_F:	SRC8 (Byte 6)	BIT 6=1 (Enable)
CR#_G:	SRC9 (Byte 6)	BIT 5=1 (Enable)
CR#_H:	SRC10 (Byte 6)	BIT 4=1 (Enable)

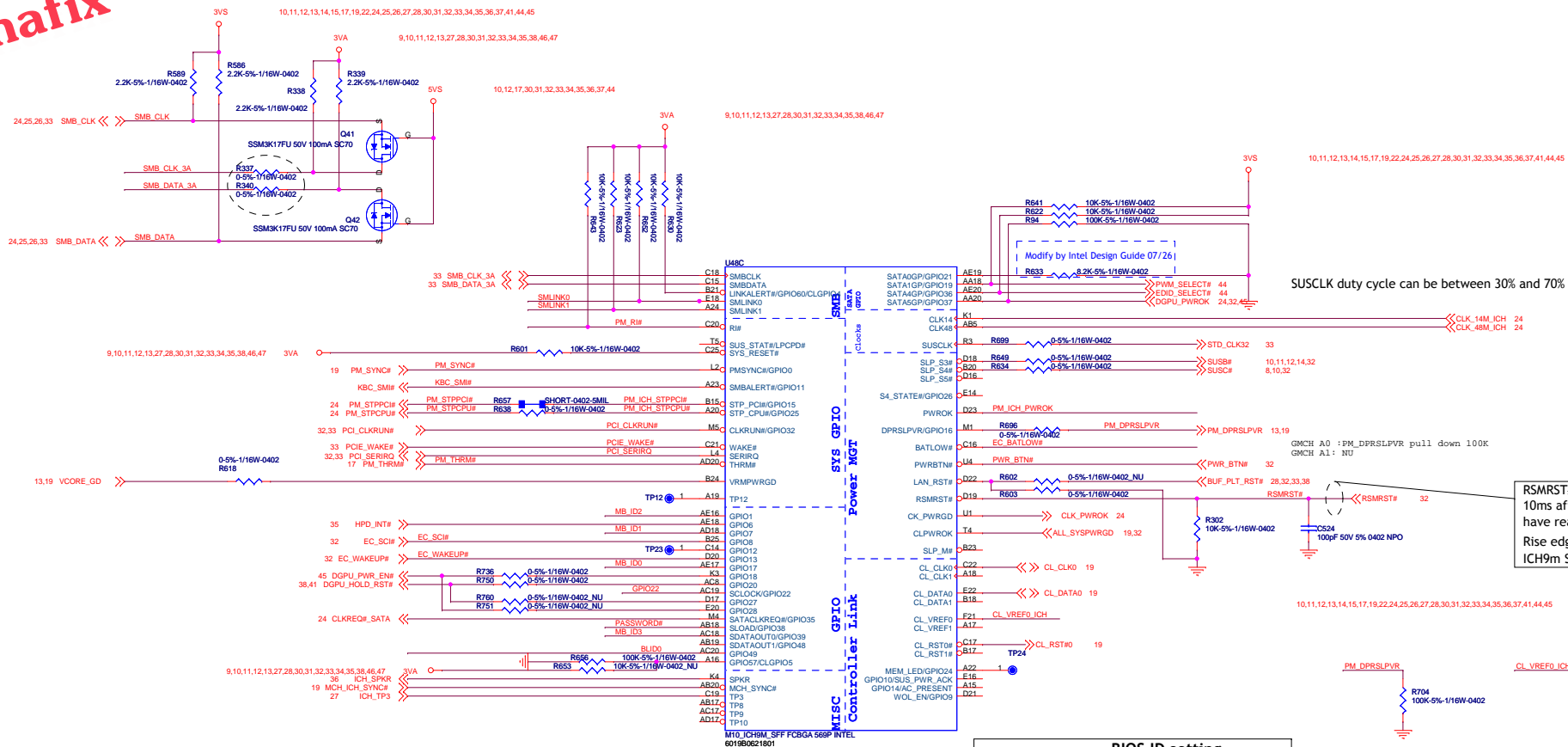








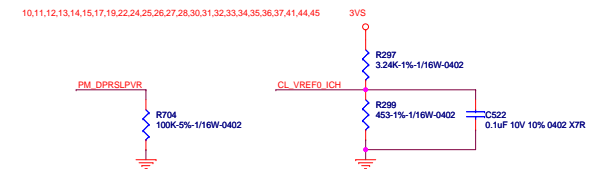




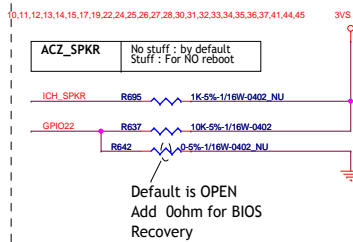
RSMRST# should go high no sooner than 10ms after both Vccsus3\_3 and Vccsus1\_5 have reached their nominal voltage

Rise edge : 1-2us

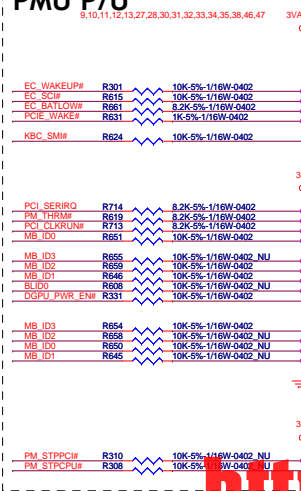
ICH9m Spec : less 50us



### ICH9m strap

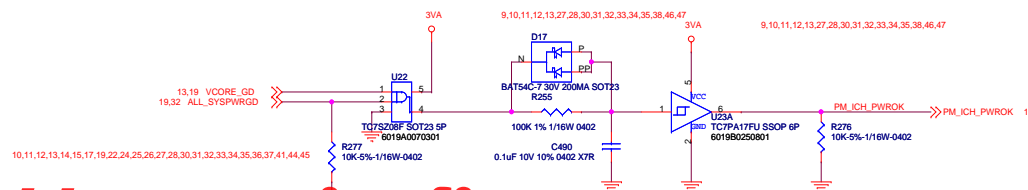
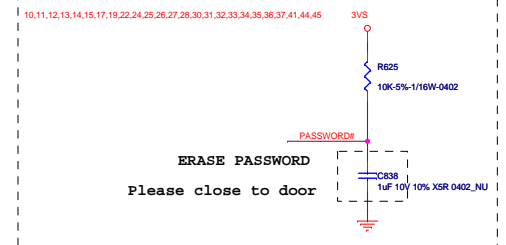


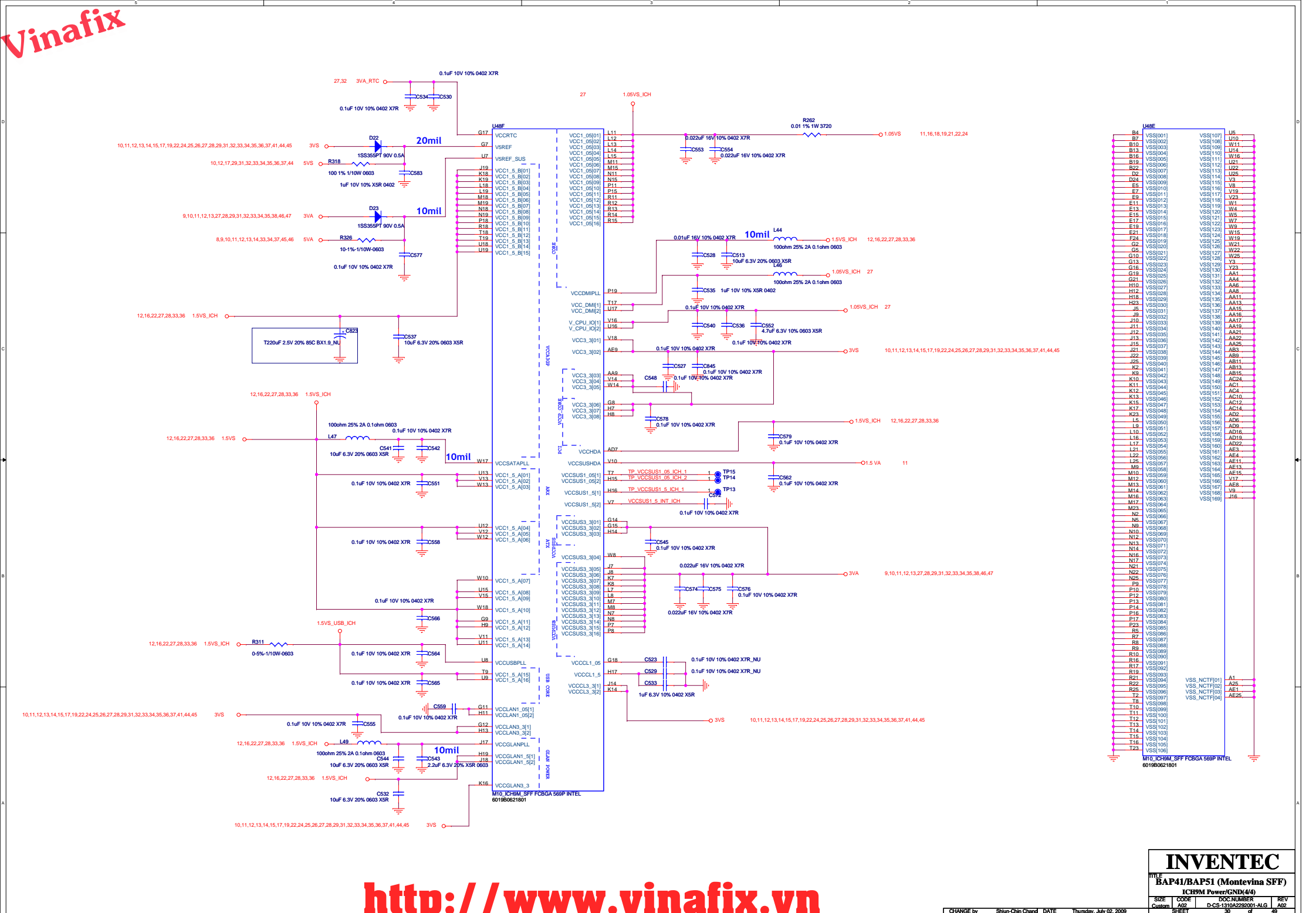
## PMU P/U

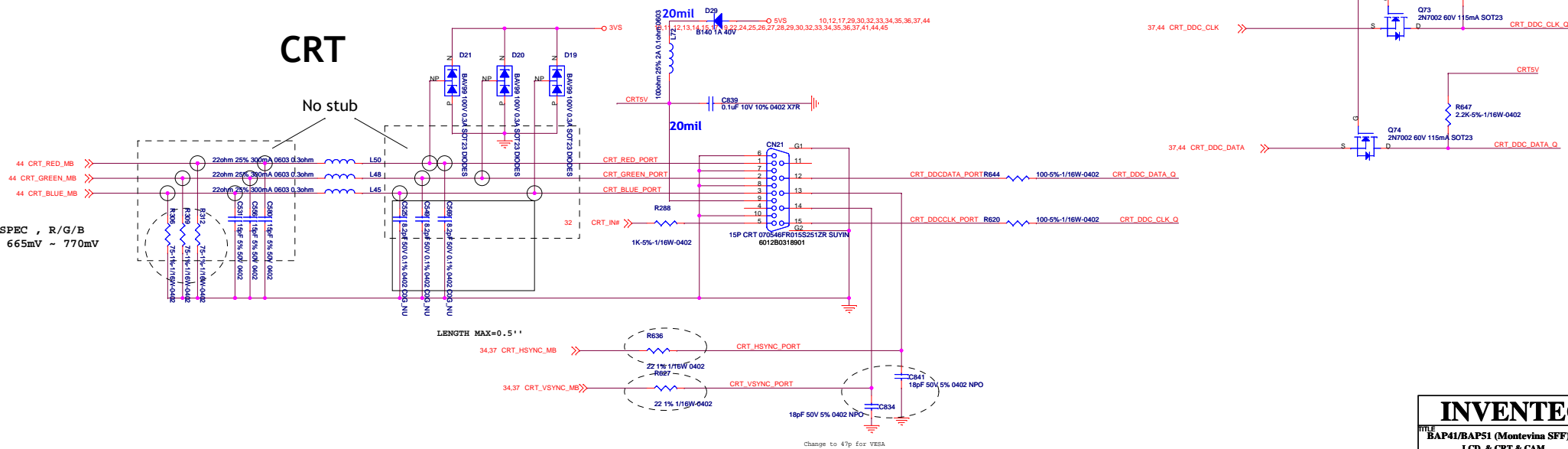
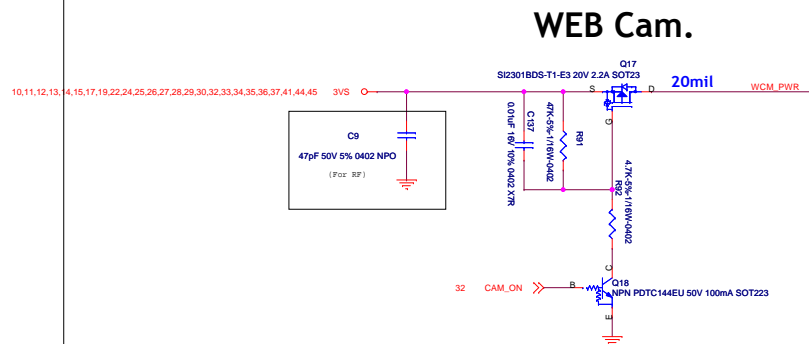
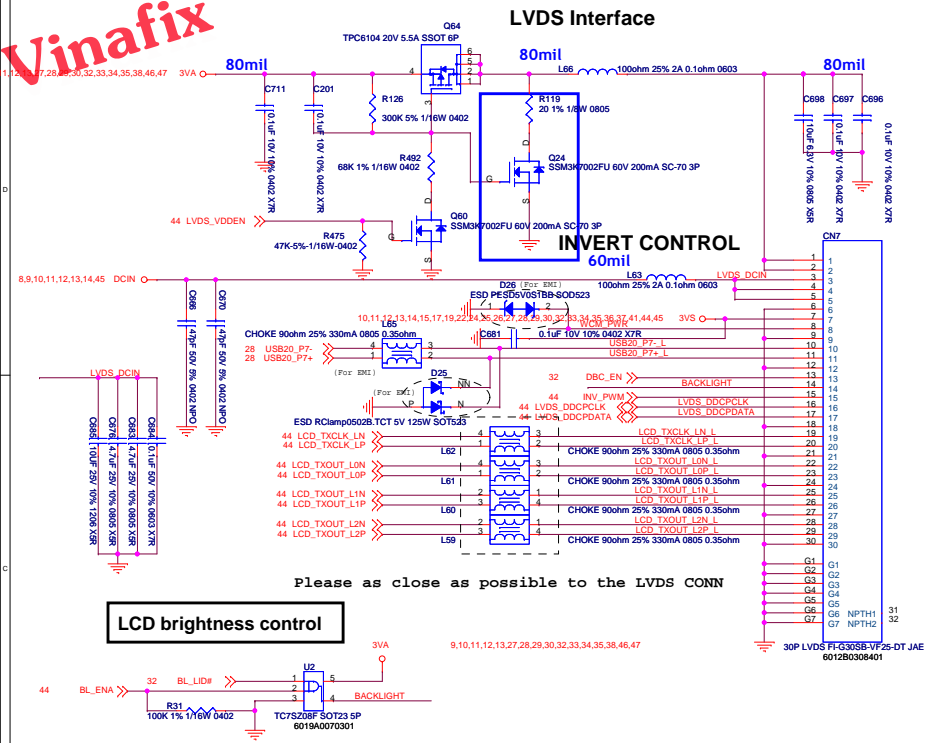


BIOS ID setting				
Project	MB_ID3	MB_ID2	MB_ID1	MB_ID0
JM31 (UMA)	1	1	1	1
SJM31 (UMA)	1	1	1	0
BAP31 (UMA)	1	1	0	1
BAP41 (UMA)	1	1	0	0
BAP51 (UMA)	1	0	1	1
JM31 (dGPU)	1	0	1	0
SJM31 (dGPU)	1	0	0	1
BAP31 (dGPU)	1	0	0	0
BAP41 (dGPU)	0	1	1	1
BAP51 (dGPU)	0	1	1	0
SJM52 (UMA)	0	1	1	0
SJM52 (dGPU)	0	1	0	0
BAP52 (UMA)	0	0	1	1
BAP52 (dGPU)	0	0	1	0
BXP41 (UMA)	0	0	0	1
BXP41 (dGPU)	0	0	0	0

## | PASSWORD CLEAR



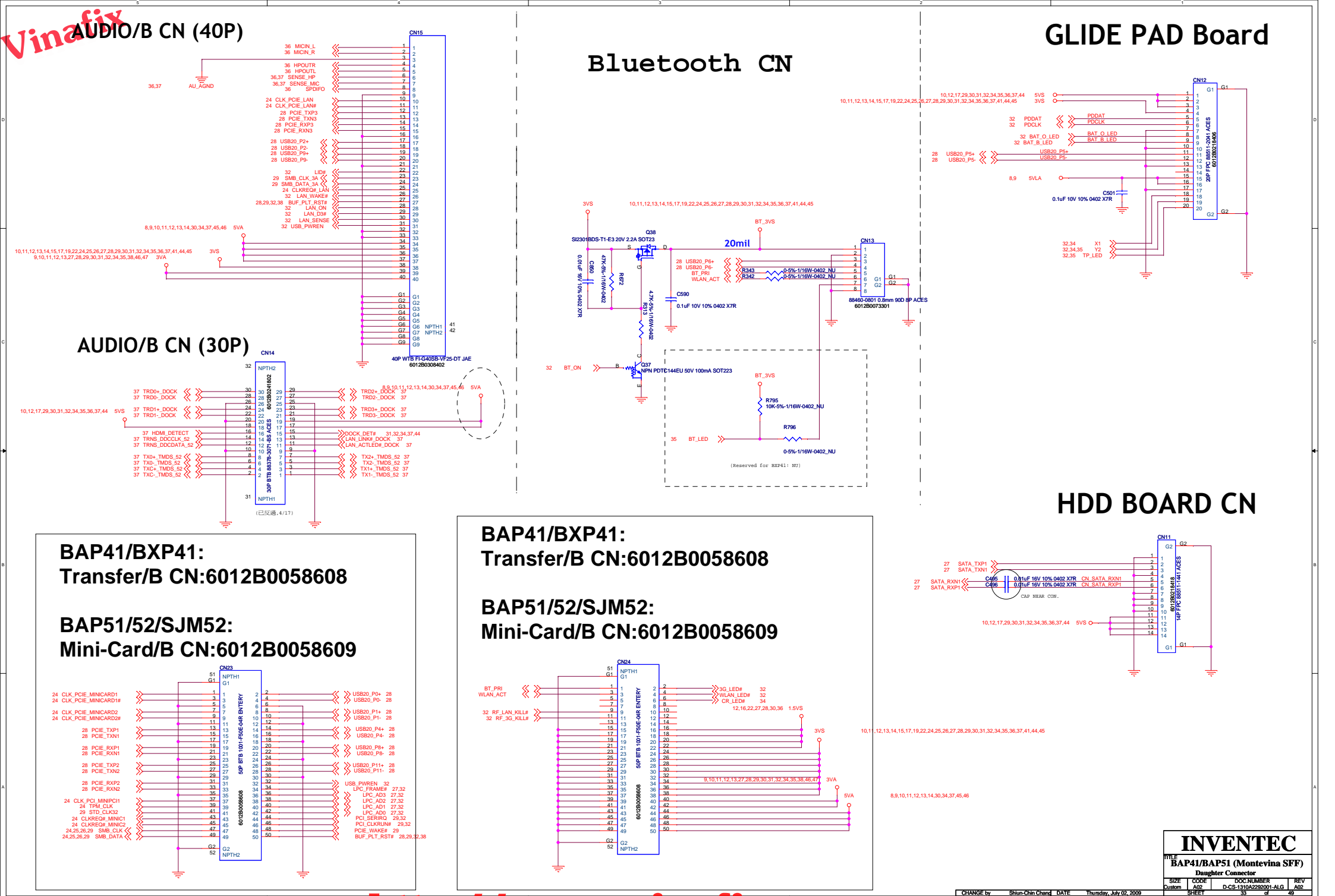






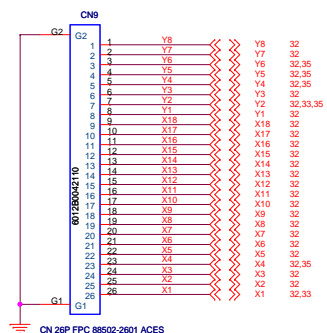




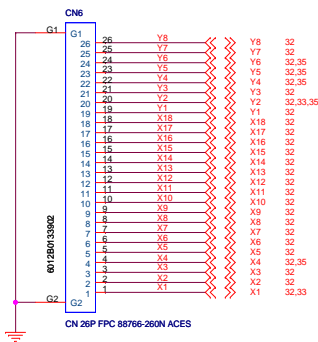


To K/B(For BAP41)

To K/B (For BAP51/BAP52/SJM52)

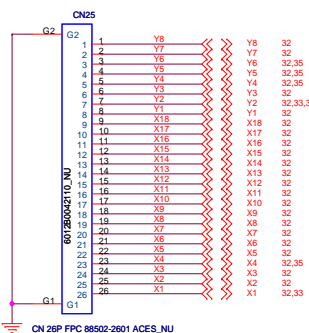


(Pin1 已反通)



(Pin1 已反通)

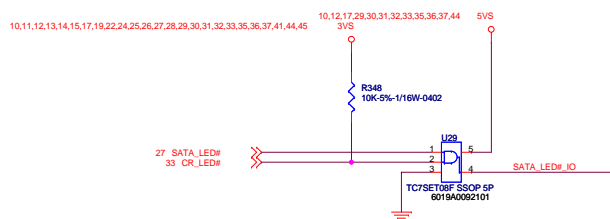
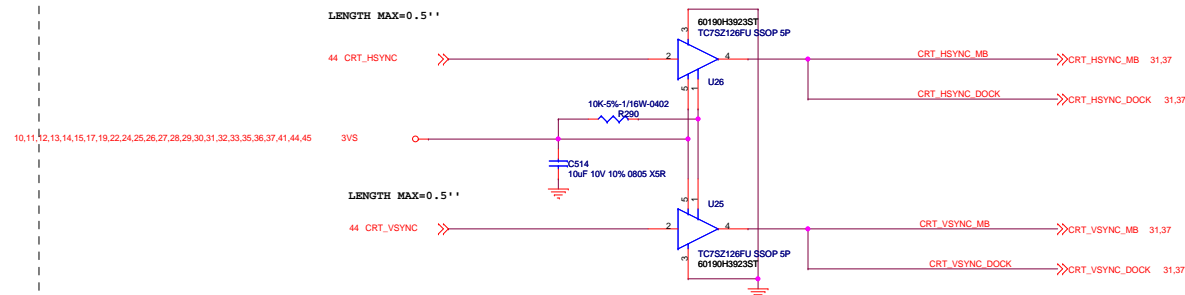
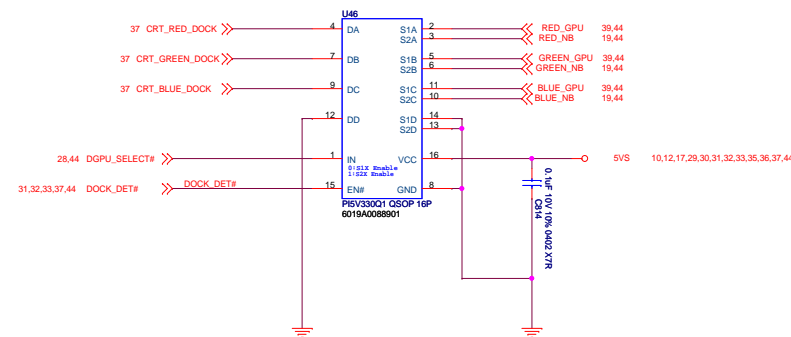
To K/B(For BXP41)



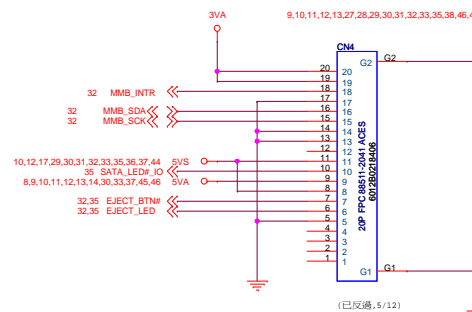
(Pin1 已反通)

BAP41/51/52/BXP41: Stuff U46,C814

SJM52 : OPEN U46,C814



SW Sensor BOARD(For SJM52)



BAP41/51/52/BXP41: OPEN  
SJM52: Stuff

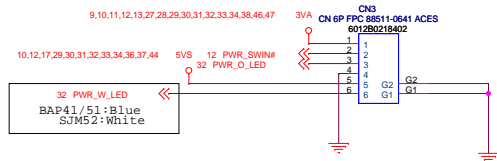
INVENTEC

FILE  
BAP41/BAP51 (Montevina SFF)  
BDP

SIZE	CODE	DOC NUMBER	REV
Custom	A02	D-GS-1310A2262001-ALG	A02
SECRET			

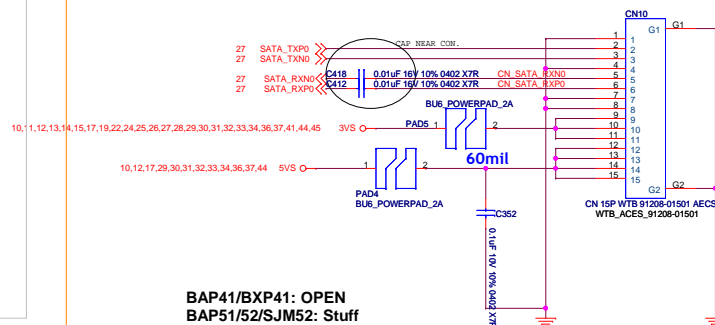
CHANGE by Shun-Chin Chang DATE Thursday, July 02, 2009

## MB(PWR\_SWIN#) TO DC-JACK/B



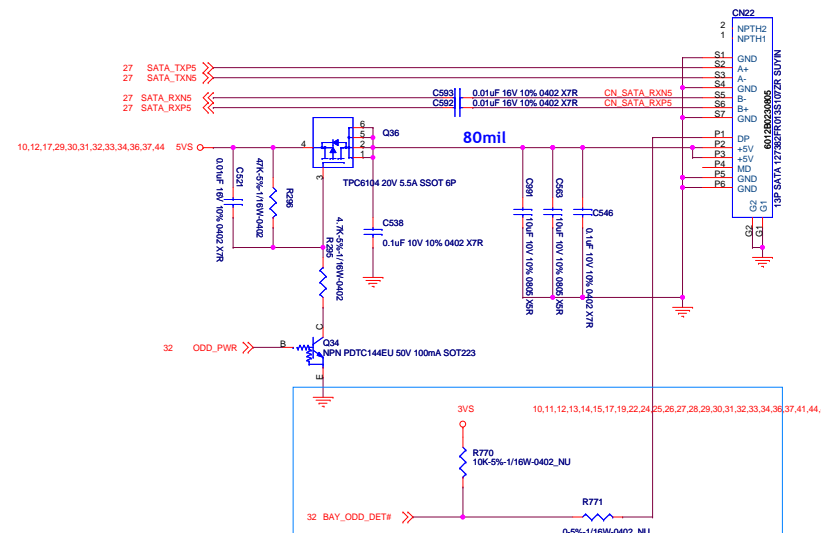
BXP41: OPEN

## SSD I/F



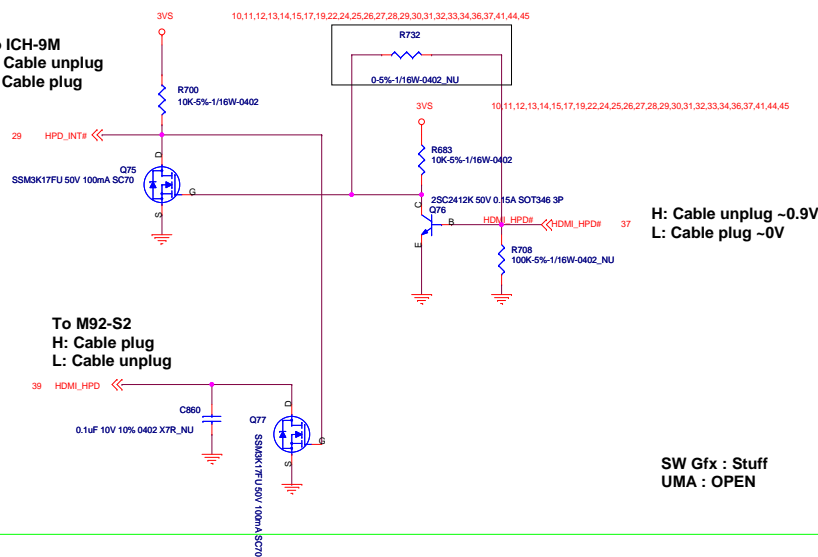
BAP41/BXP41: OPEN  
BAP51/52/SJM52: Stuff

## ODD I/F



For BAP52 : Stuff

To ICH-9M  
H: Cable unplug  
L: Cable plug



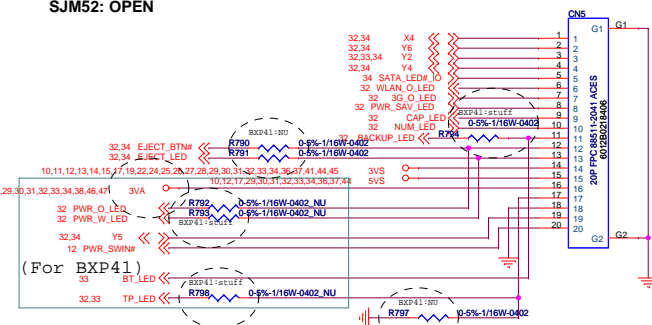
H: Cable unplug -0.9V  
L: Cable plug -0V

To M92-S2  
H: Cable plug  
L: Cable unplug

SW Gfx : Stuff  
UMA : OPEN

## SW/B CN

BAP41/51/52/BXP41: Stuff  
SJM52: OPEN



SW Gfx : OPEN  
UMA : Stuff

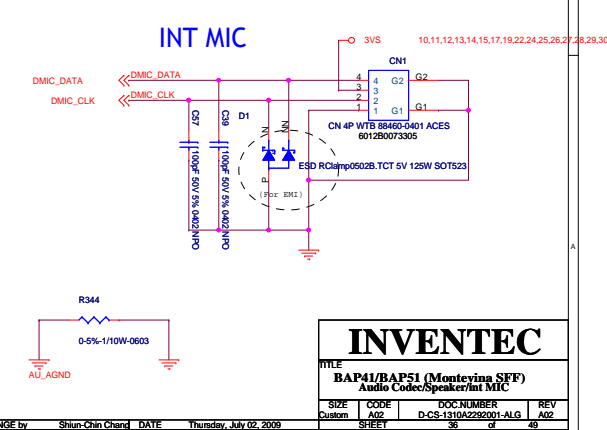
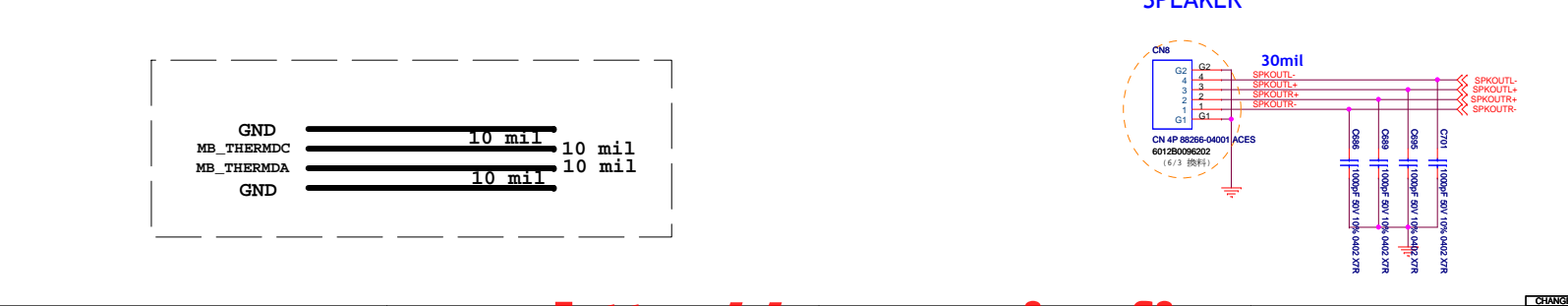
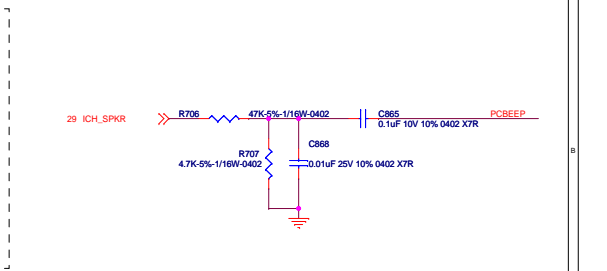
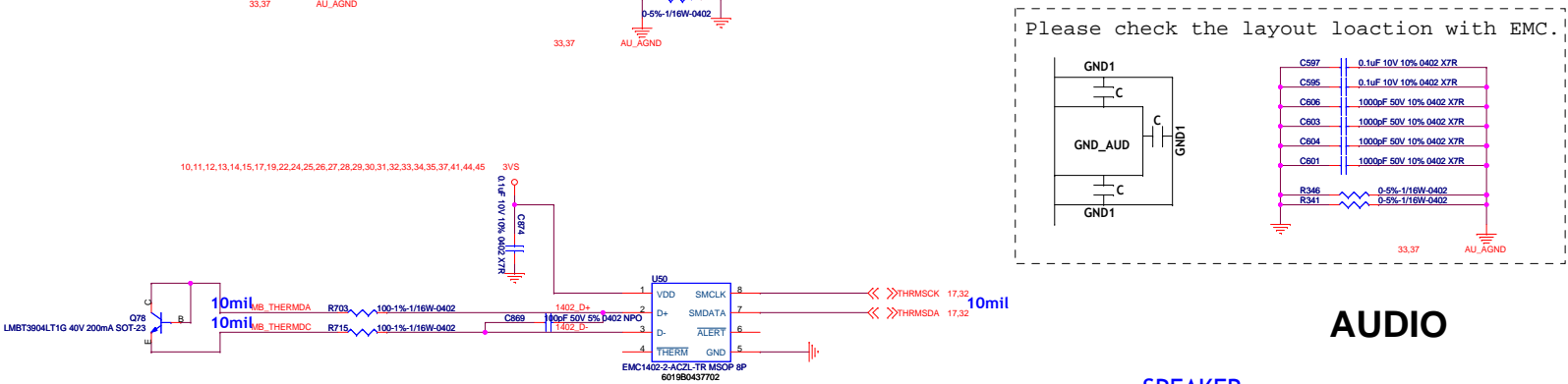
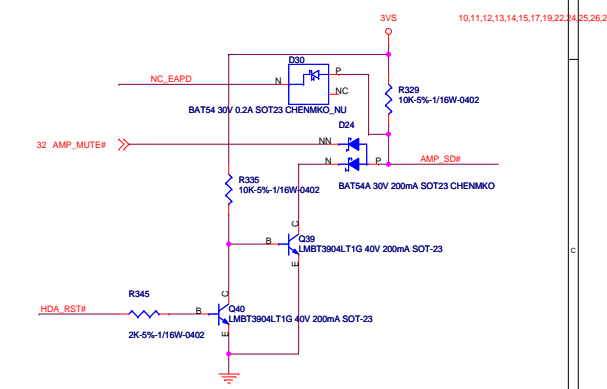
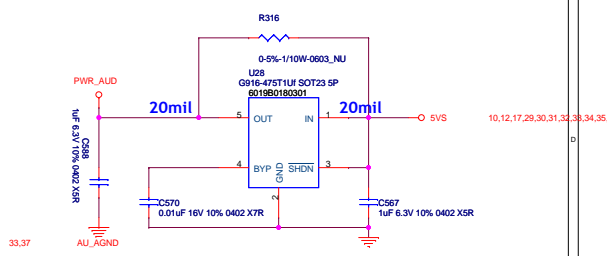
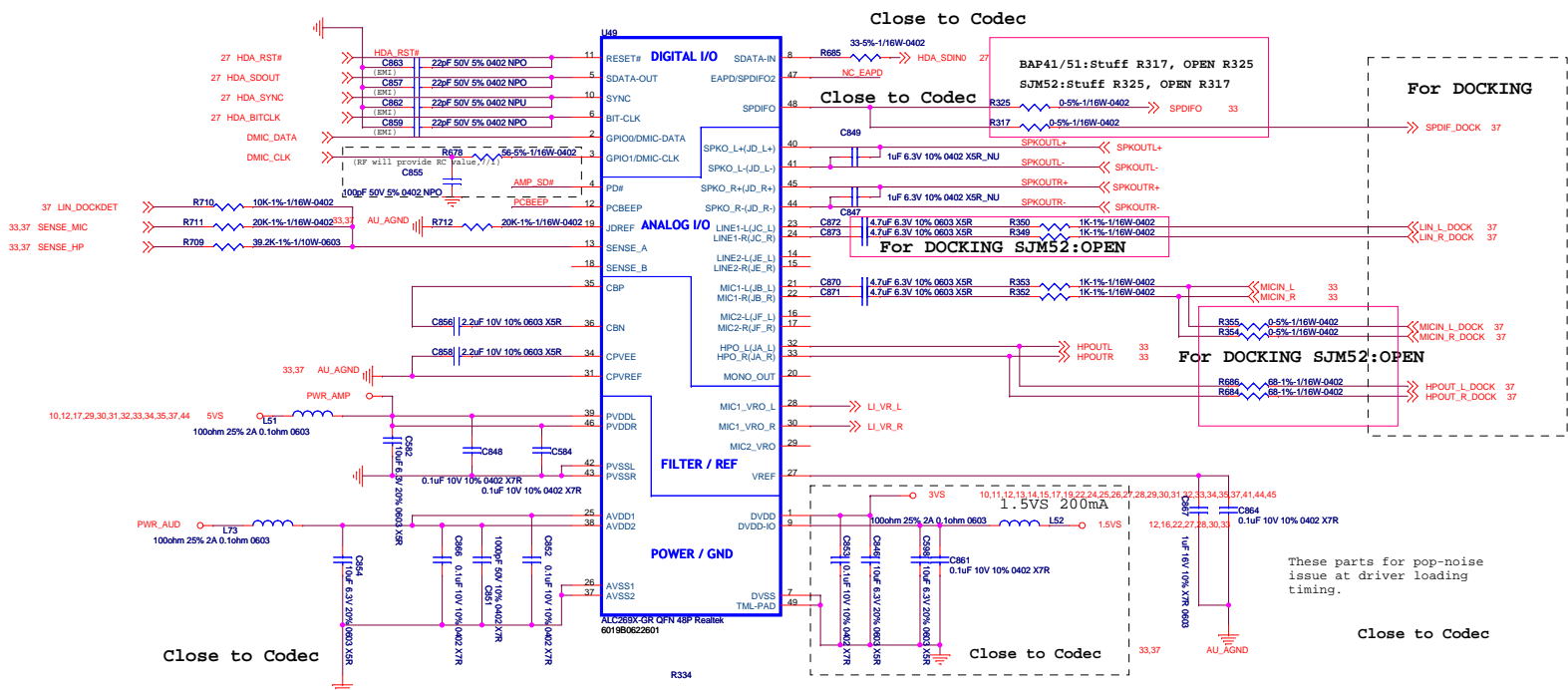
Size:0201

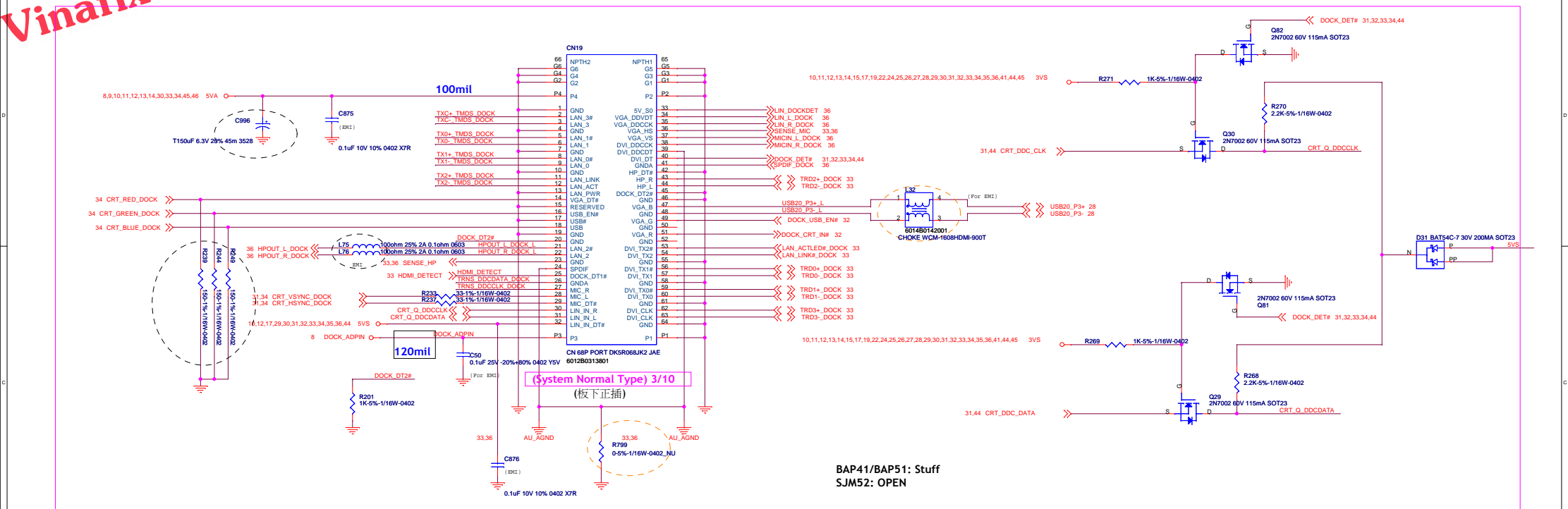
INVENTEC

FILE  
BAP41/BAP51 (Montevina SFF)  
BDP

SIZE	CODE	DOC NUMBER	REV
Custom	A02	D-GS-1310A2220001-ALG	A02
Sheet	35	9	49

CHANGE by Shun-Chin Chang DATE Thursday, July 02, 2009





Layout Note: 2 components with one mutual pad, total 3 pads

SW Gfx:OPEN, UMA: Stuff

SW Gfx:Stuff, UMA: OPEN

Place close to U16(PI3VDP411LSTZBEX)

SW Gfx:Stuff  
UMA: OPEN

SW Gfx:OPEN  
UMA: Stuff

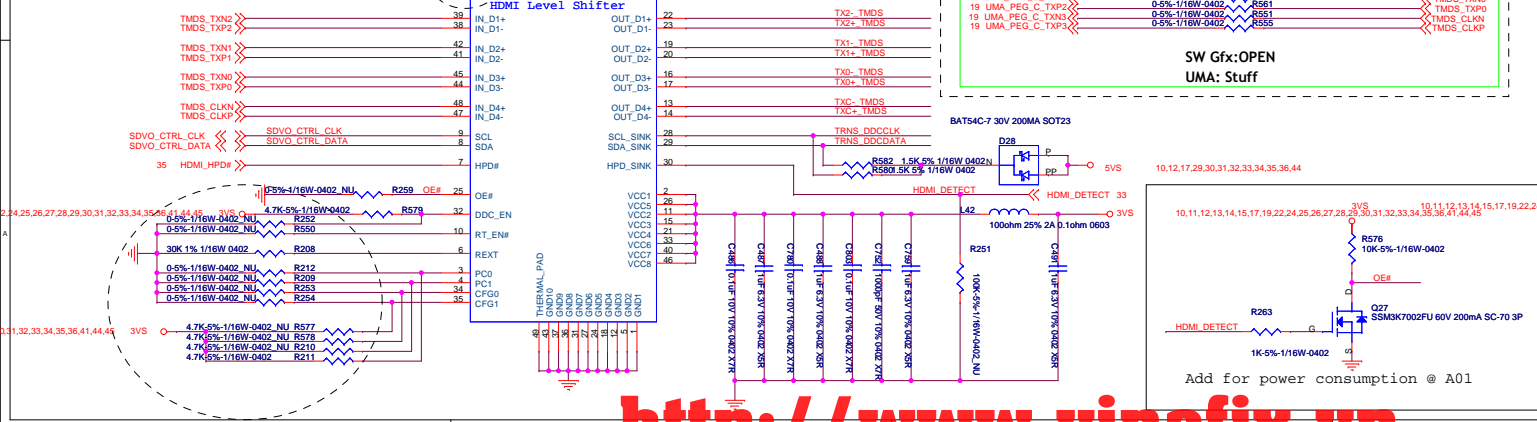
Place close to U16(PI3VDP411LSTZBEX)

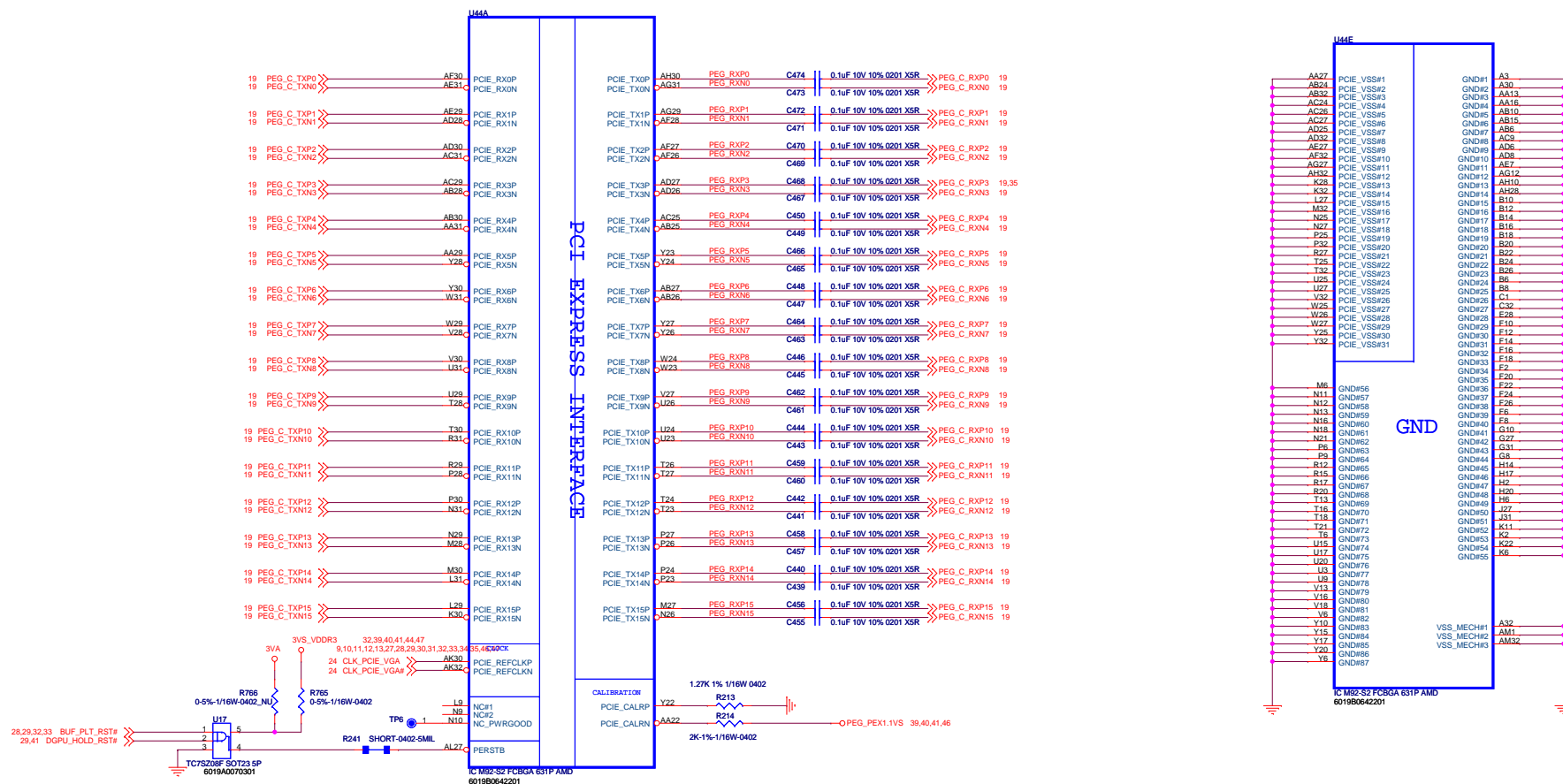
**BAP41/BAP51: Stuff**  
**SJM52: OPEN**

**BAP41/BAP51: OPEN**  
**SJM52: Stuff**

Parade	Pericom
U16 : 6019B0585301	6019B0443802
R550 : OPEN	0 ohm
R208 : OPEN	0 ohm
R212 : OPEN	0 ohm
R209 : OPEN	0 ohm
R253 : OPEN	0 ohm
R577 : OPEN	4.7K
R211 : 4.7K	OPEN

Note: R208: SJM52 is not 30K



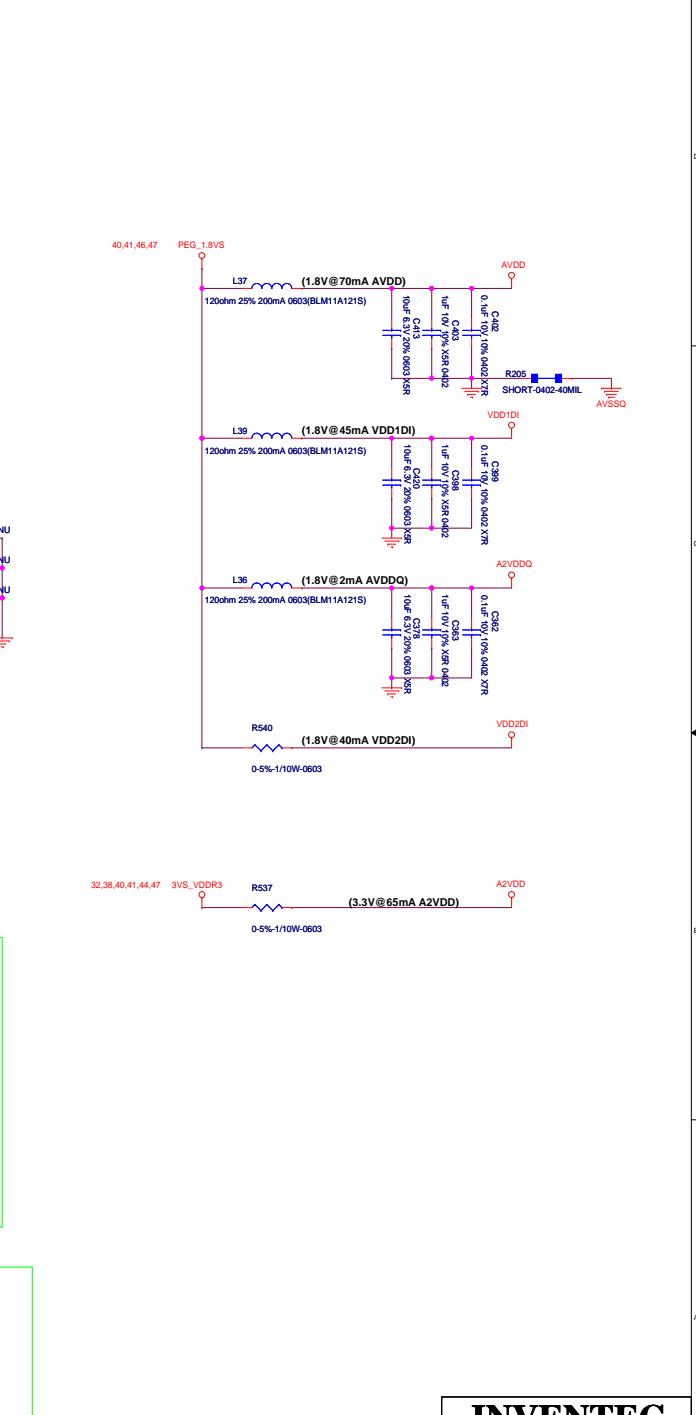
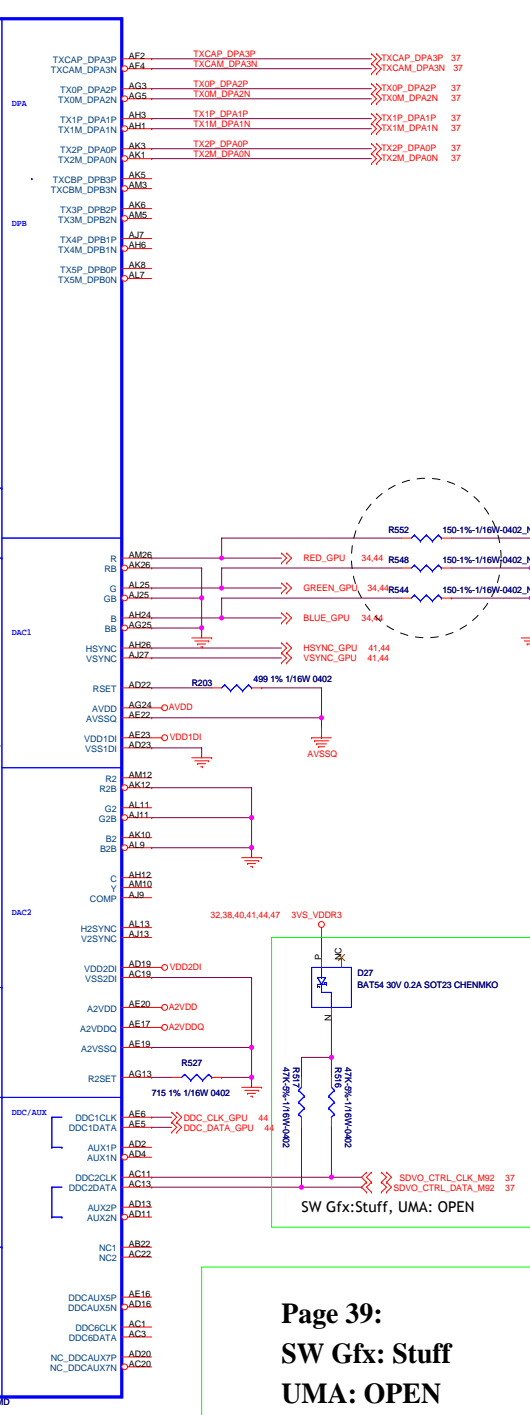
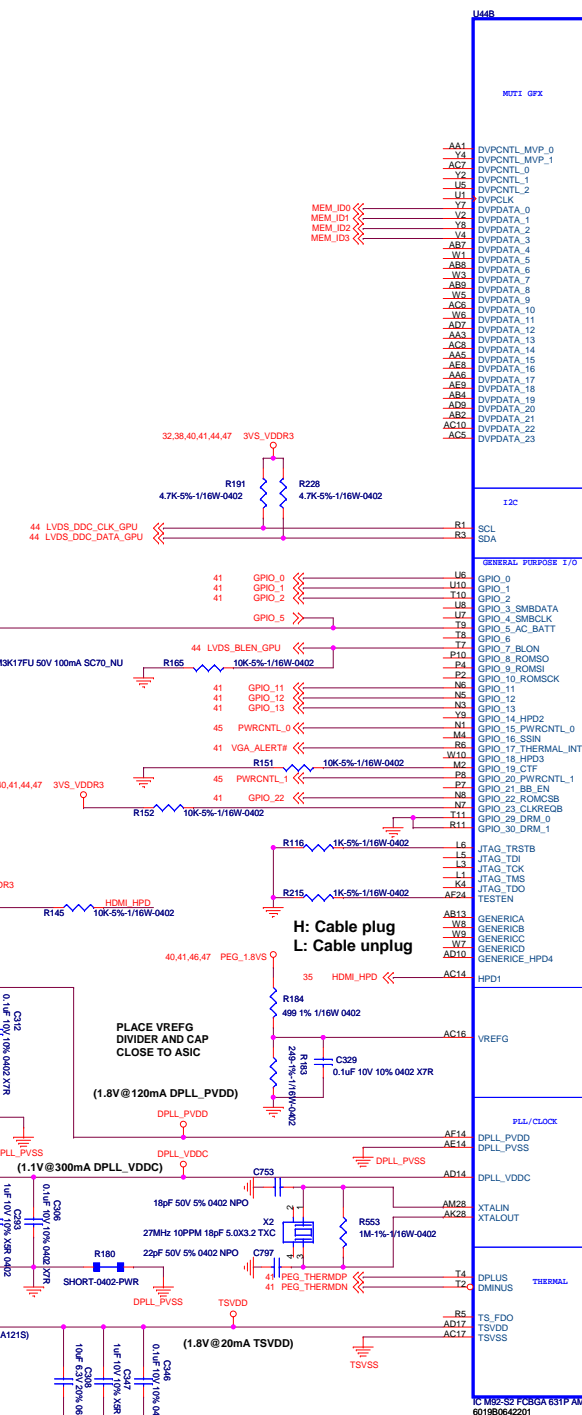
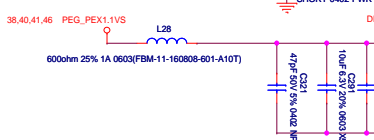
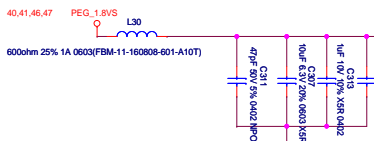
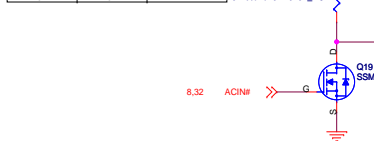


GPIO_13	GPIO_12	GPIO_11	For DDR3
0	0	0	128M
0	0	1	256M(Default)
1	1	0	Reserved

MEM_ID3	MEM_ID2	MEM_ID1	MEM_ID0	VENDOR
0	0	0	0	Hynix 64Mx16
1	0	0	0	Samsung 64Mx16

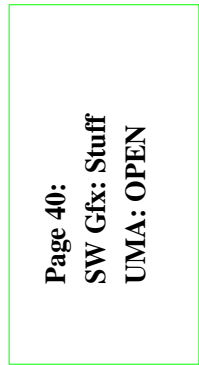


PWRCNTL_1	PWRCNTL_0	VDDC
1	1	0.9V
1	0	0.95V
0	1	1.05V
0	0	1.1V



Page 39:  
SW Gfx: Stuff  
UMA: OPEN

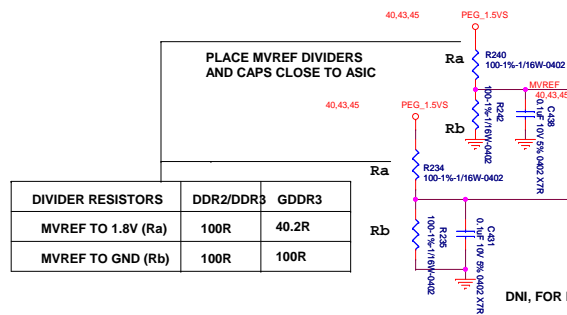






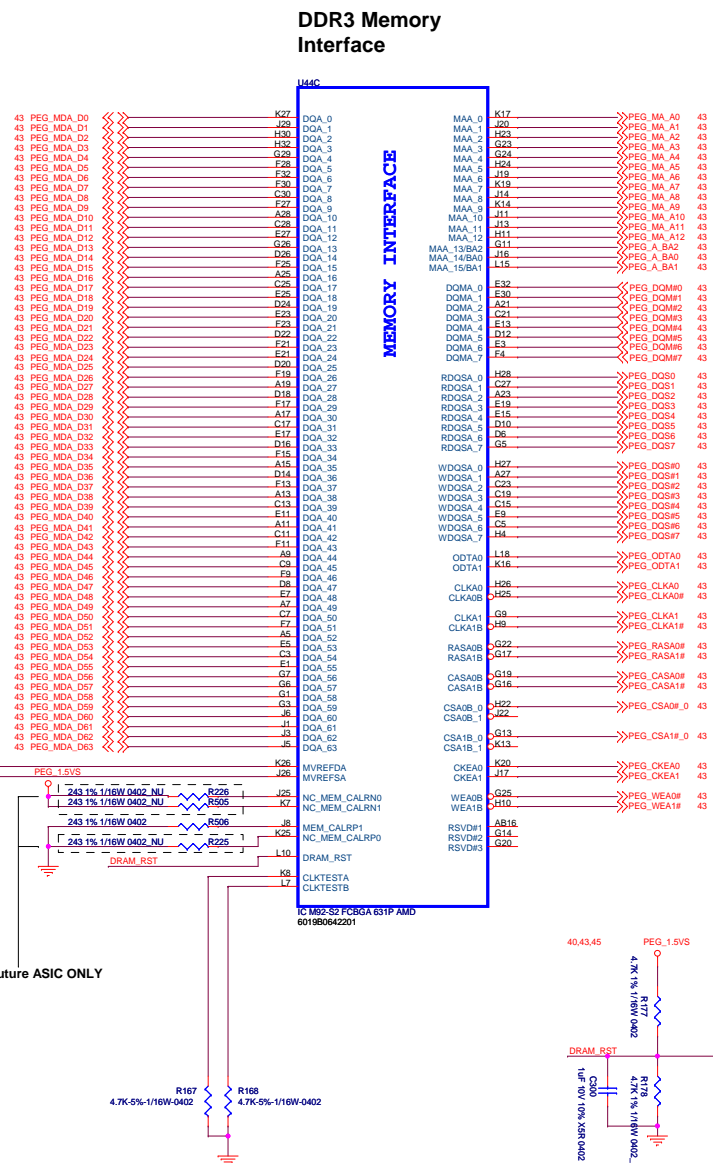


**MVDDQ = 1.5V FOR  
DDR3 Memory**

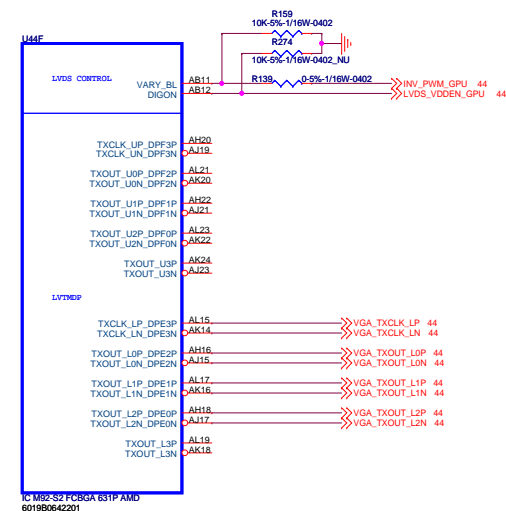


DIVIDER RESISTORS	DDR2/DDR3	GDDR3
MVREF TO 1.8V (Ra)	100R	40.2R
MVREF TO GND (Rb)	100R	100R

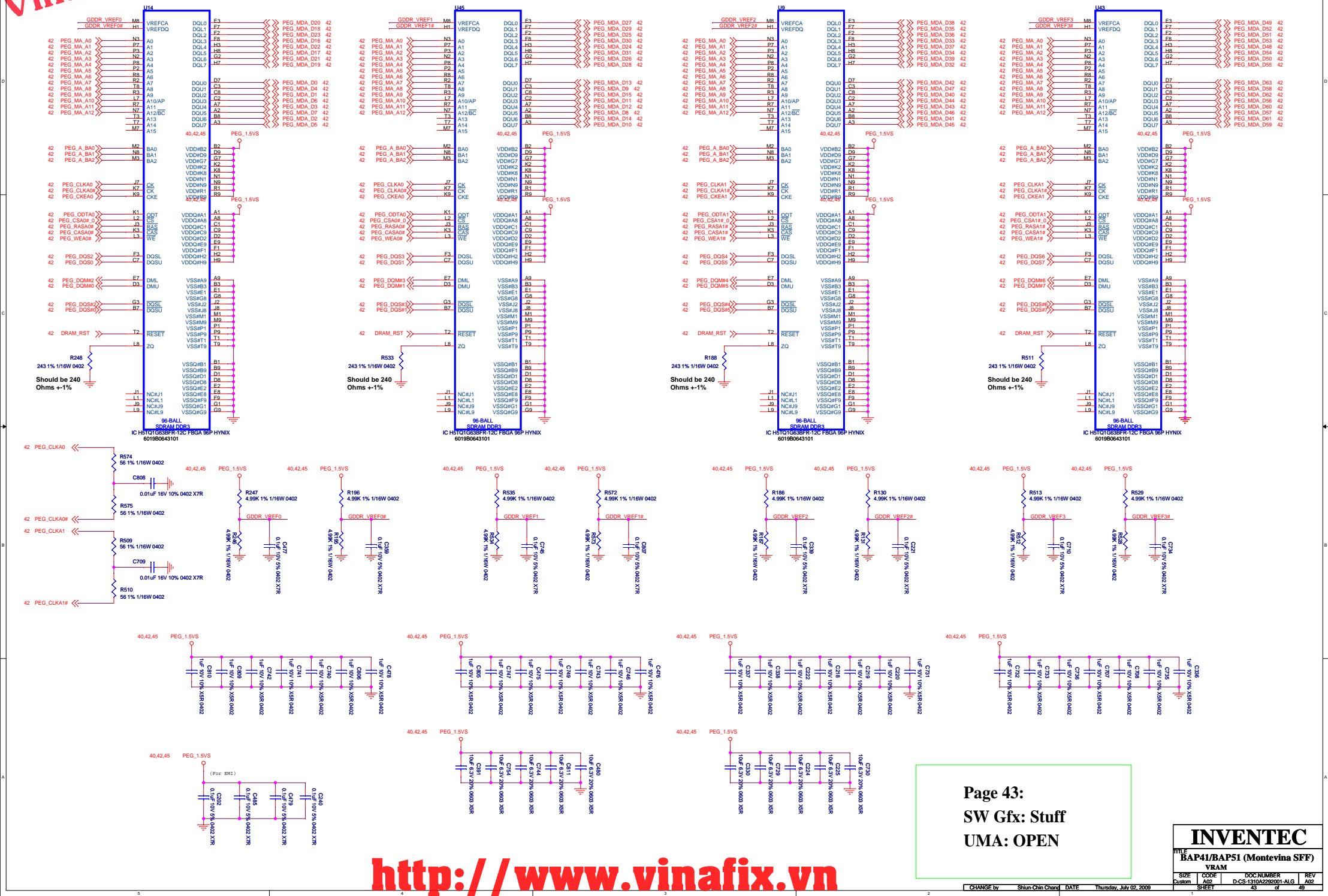
DNI, FOR Future ASIC ONLY



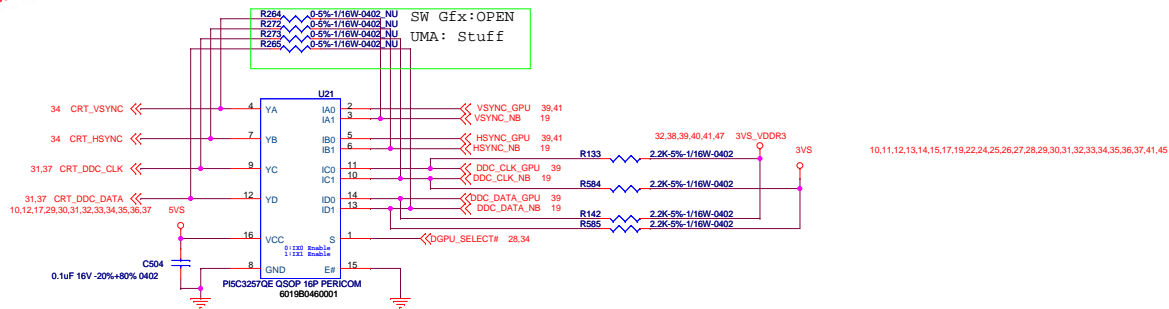
## LVDS Interface



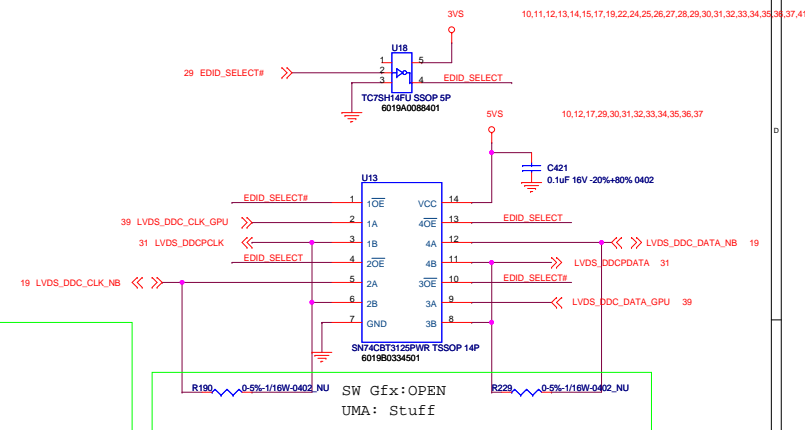
**Page 42:**  
**SW Gfx: Stuff**  
**UMA: OPEN**



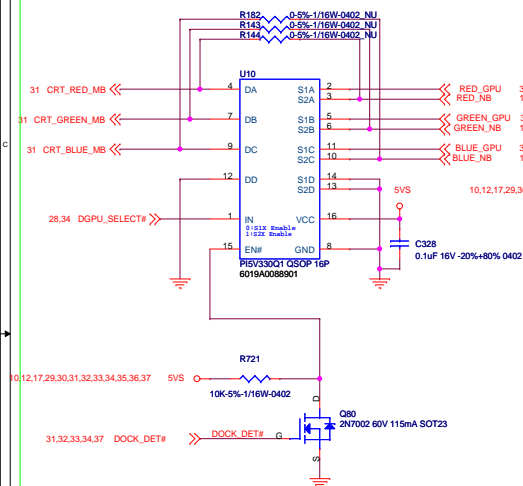
## CRT HSYNC/VSYSN/DDC SW



## LCD DDC SW

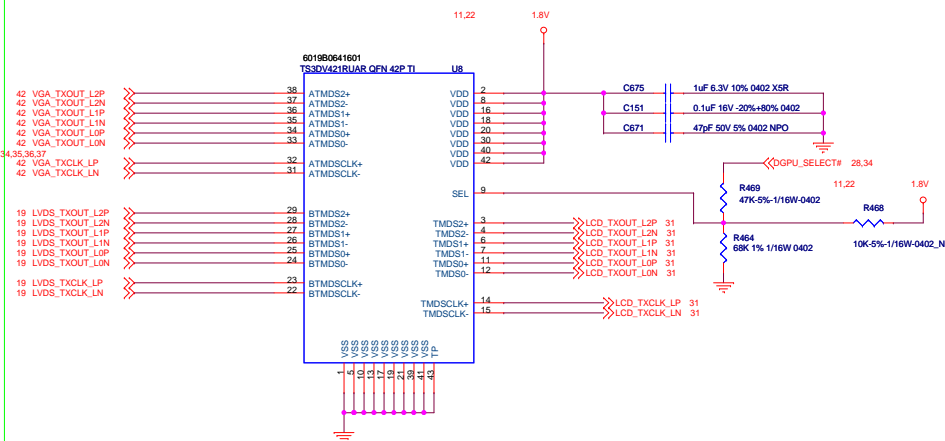


## CRT R/G/B SW



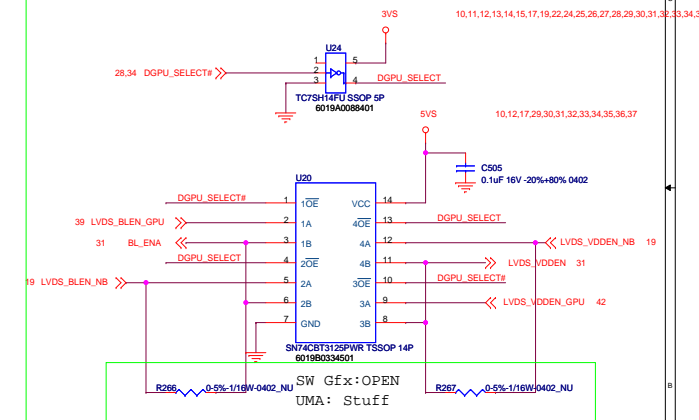
Stuff CRT/RGB SW for both SW Gfx and UMA  
SW Gfx : Stuff U10,C328,R721,Q80  
UMA : Stuff U10,C328,R721,Q80

## LVDS SW

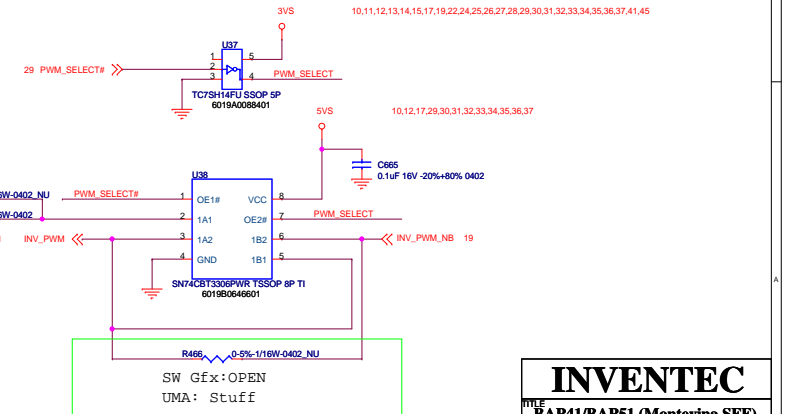


Thermal Pad limitation : Stuff LVDS SW for both SW Gfx and UMA  
SW Gfx : Stuff U8,C675,C151,C671,R469,R464, OPEN R468  
UMA : Stuff U8,C675,C151,C671,R468, OPEN R469,R464

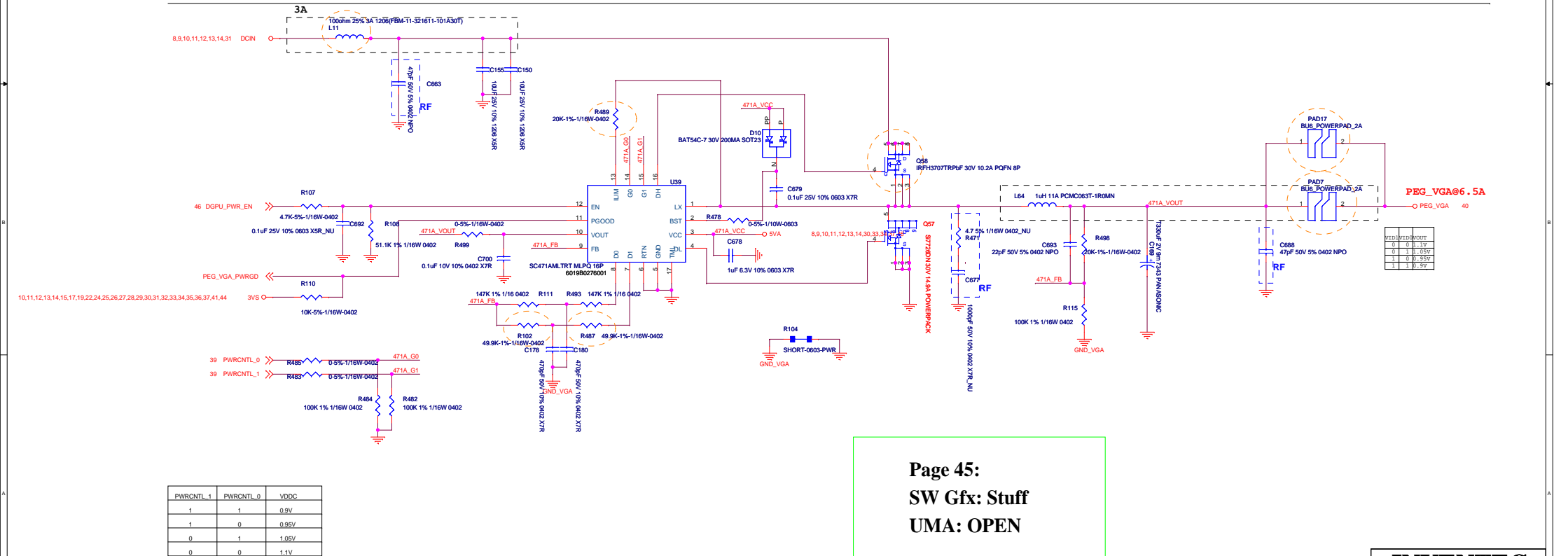
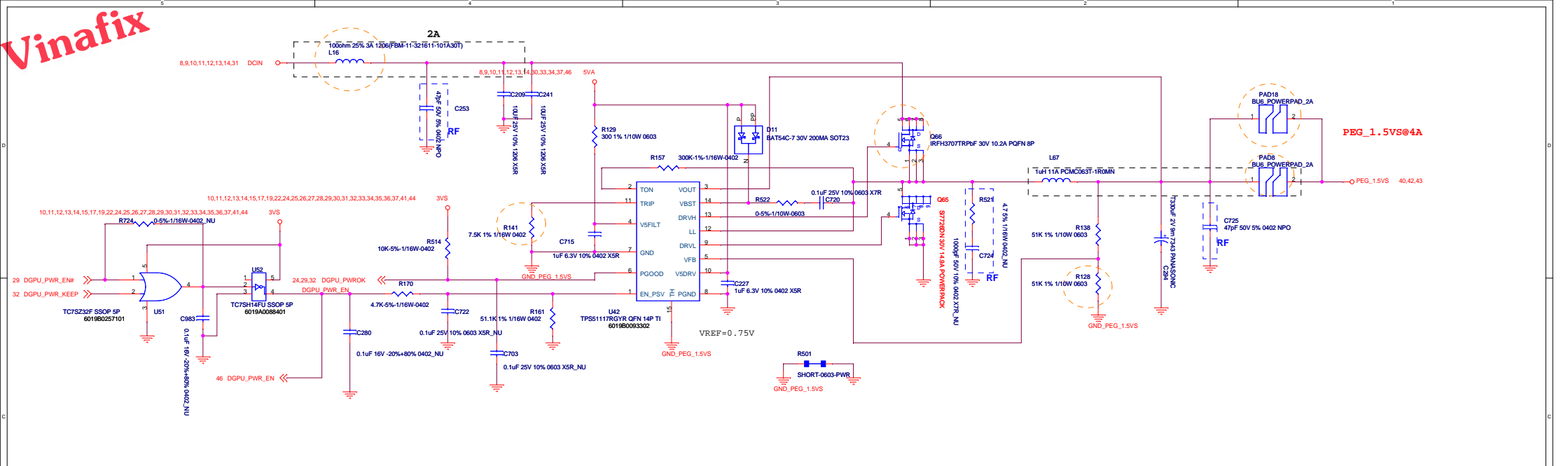
## LVDS BKL and Vcc Enable SW



## LCD PWM SW

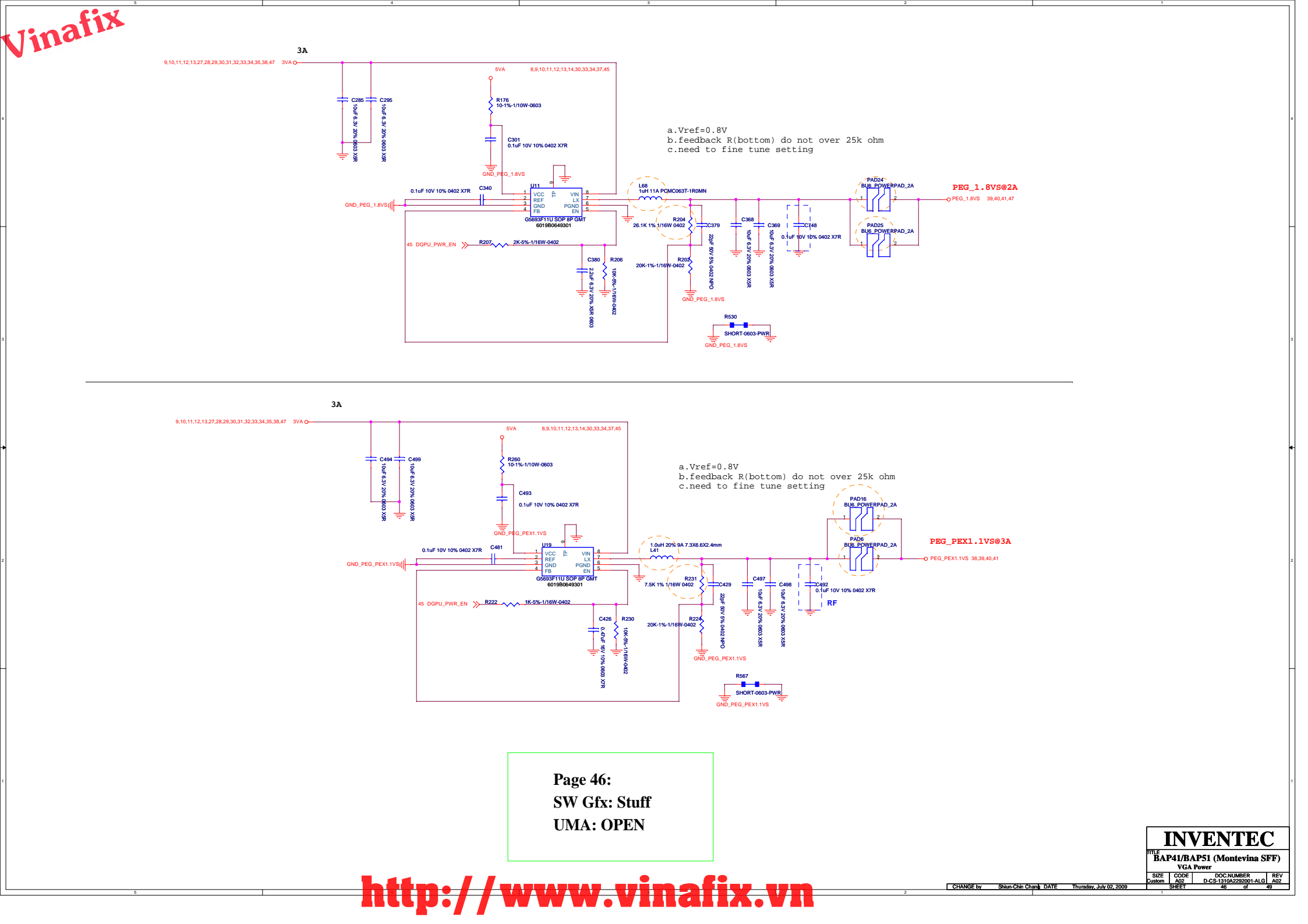


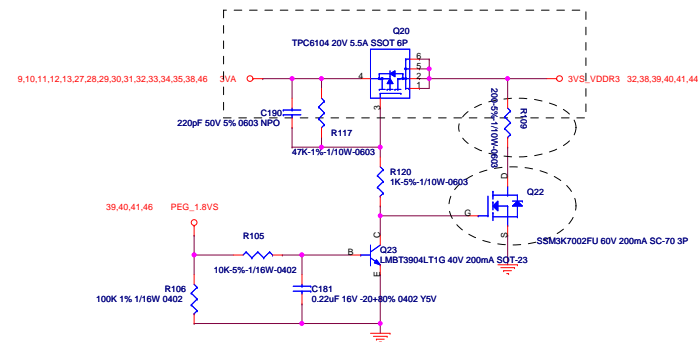
Page 44:  
SW Gfx: Stuff  
UMA: OPEN



PWRCTRL_1	PWRCTRL_0	VDDC
1	1	0.9V
1	0	0.95V
0	1	1.05V
0	0	1.1V

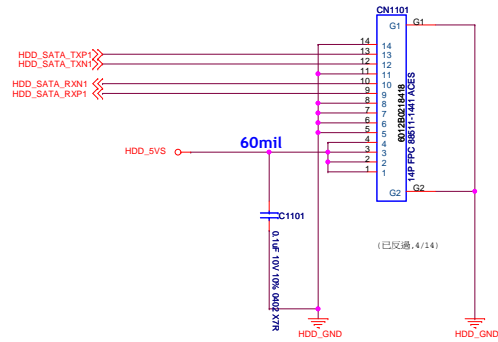
Page 45:  
SW Gfx: Stuff  
UMA: OPEN



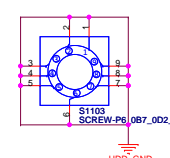
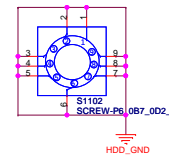
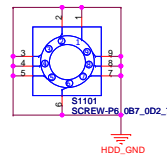
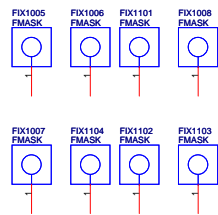
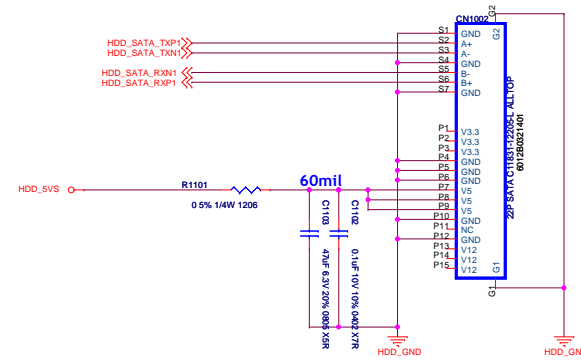


Page 47:  
SW Gfx: Stuff  
UMA: OPEN

## HDD Board CN TO MB

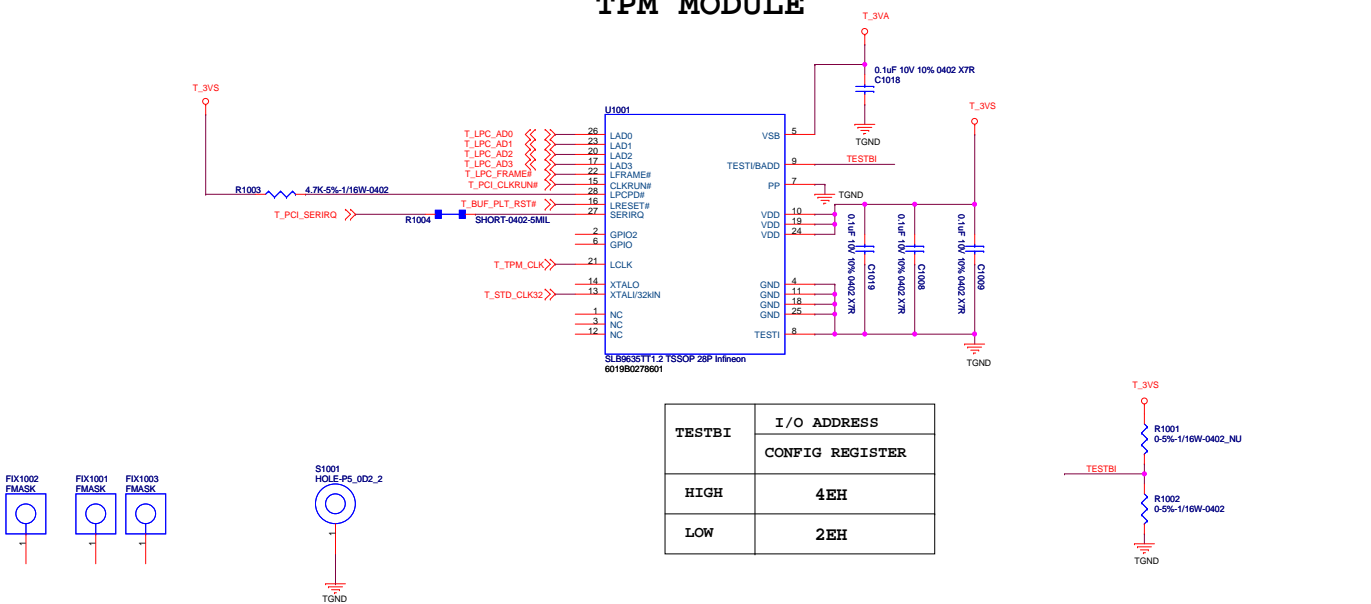


## HDD I/F





# TPM MODULE



TESTBI	I/O ADDRESS
	CONFIG REGISTER
HIGH	4EH
LOW	2EH

## TO MINI-CARD/B

